

FIG.1

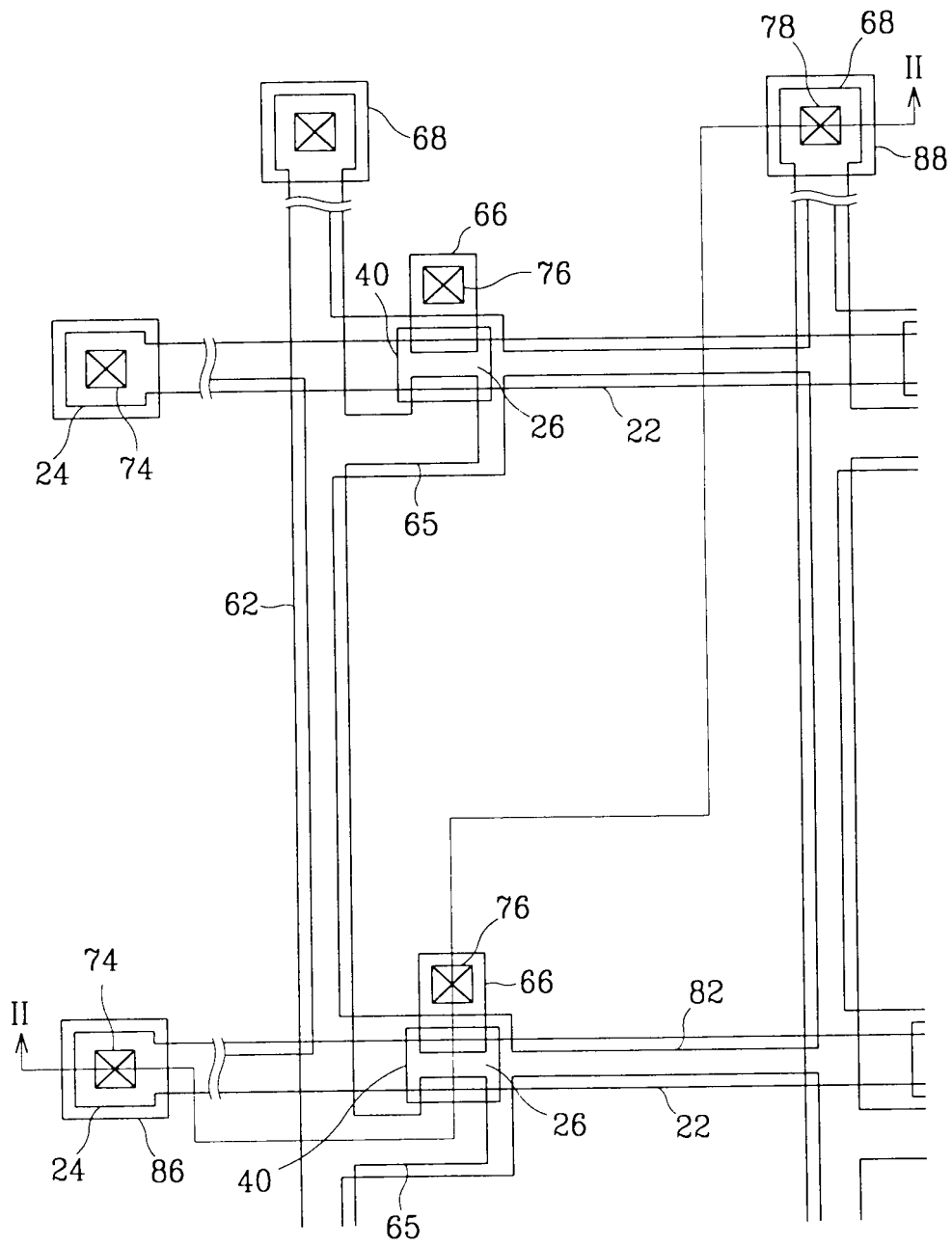


FIG. 2

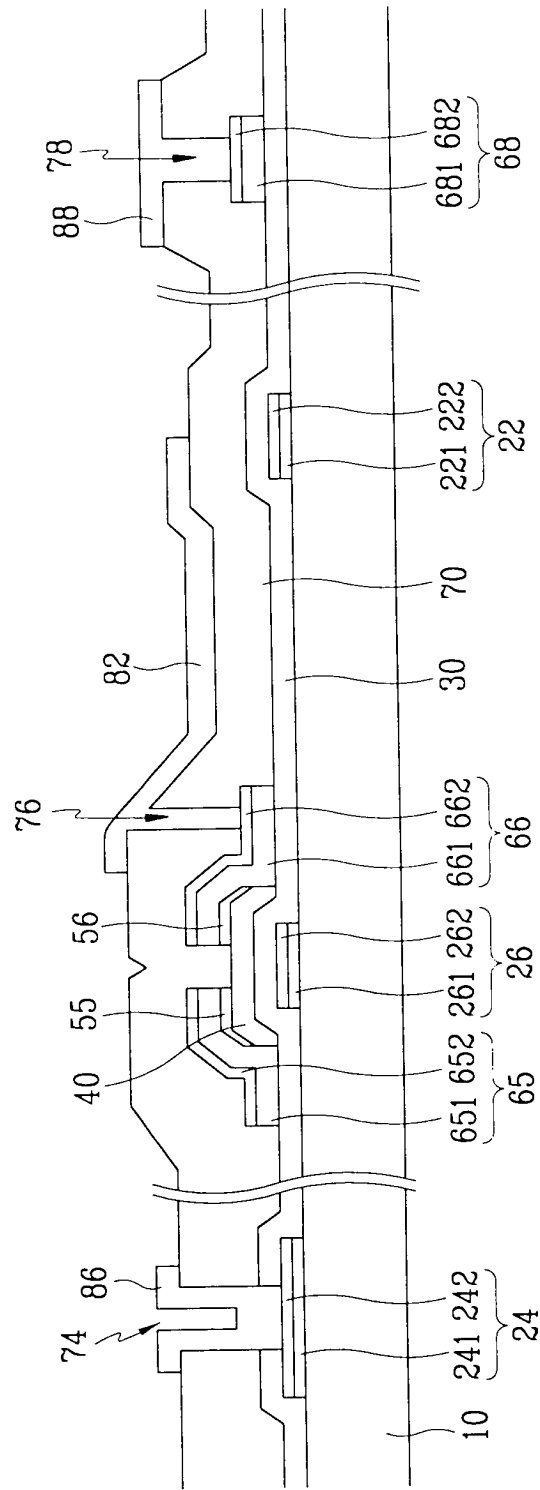


FIG.3A

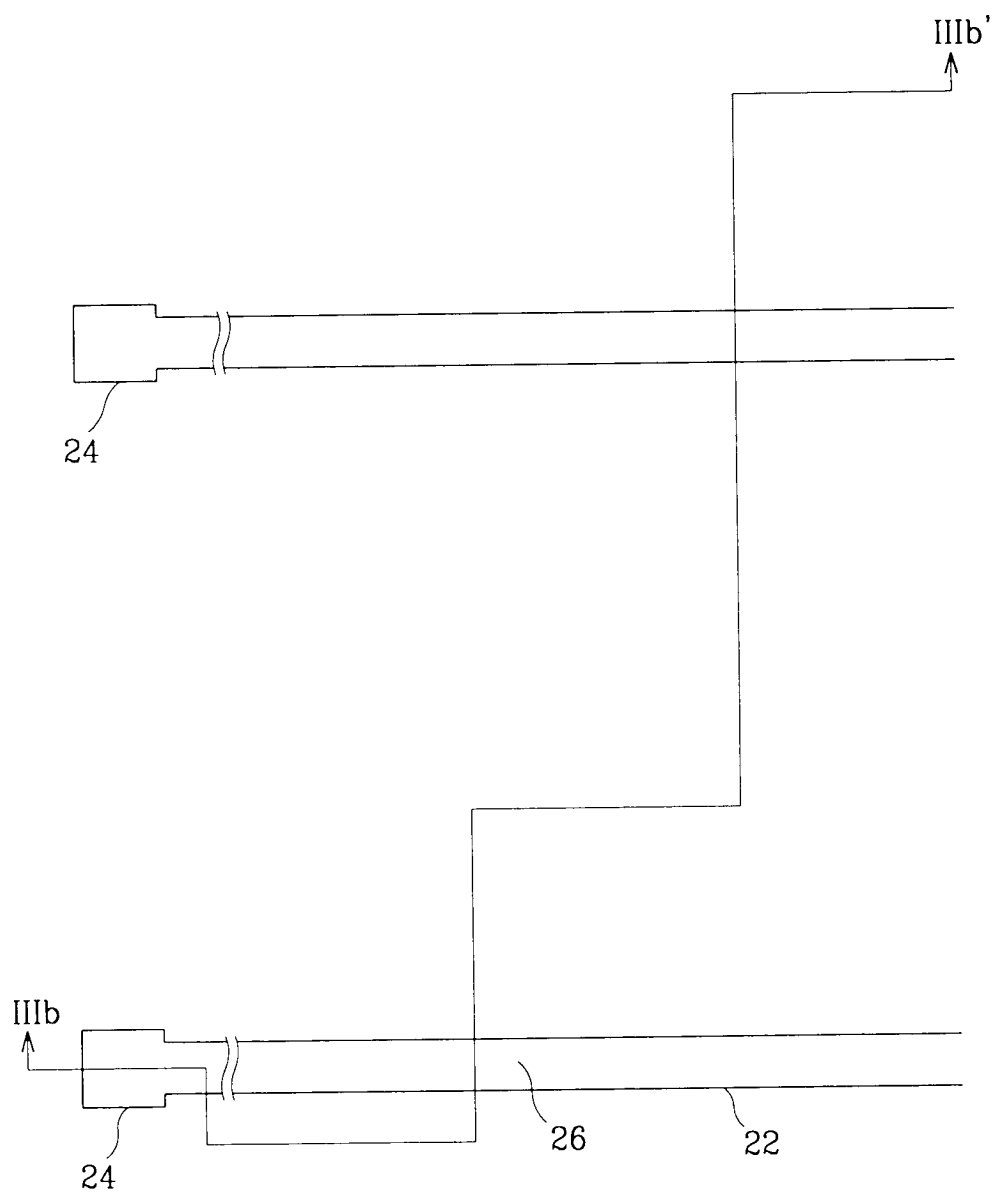


FIG. 3B

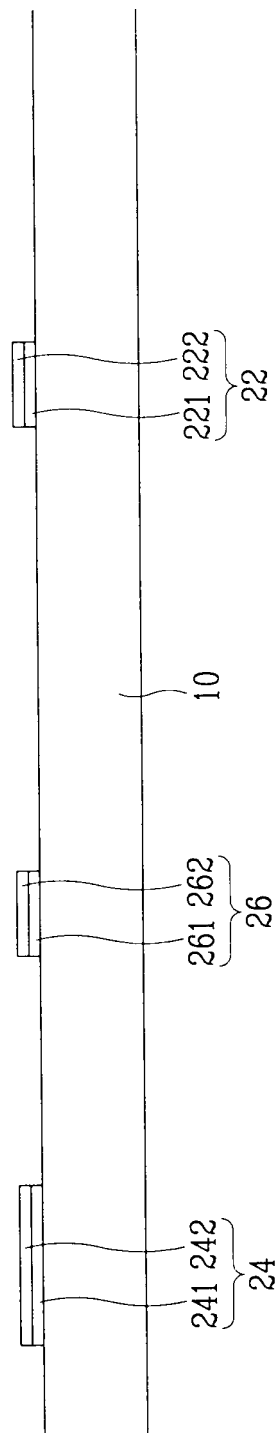


FIG. 4A

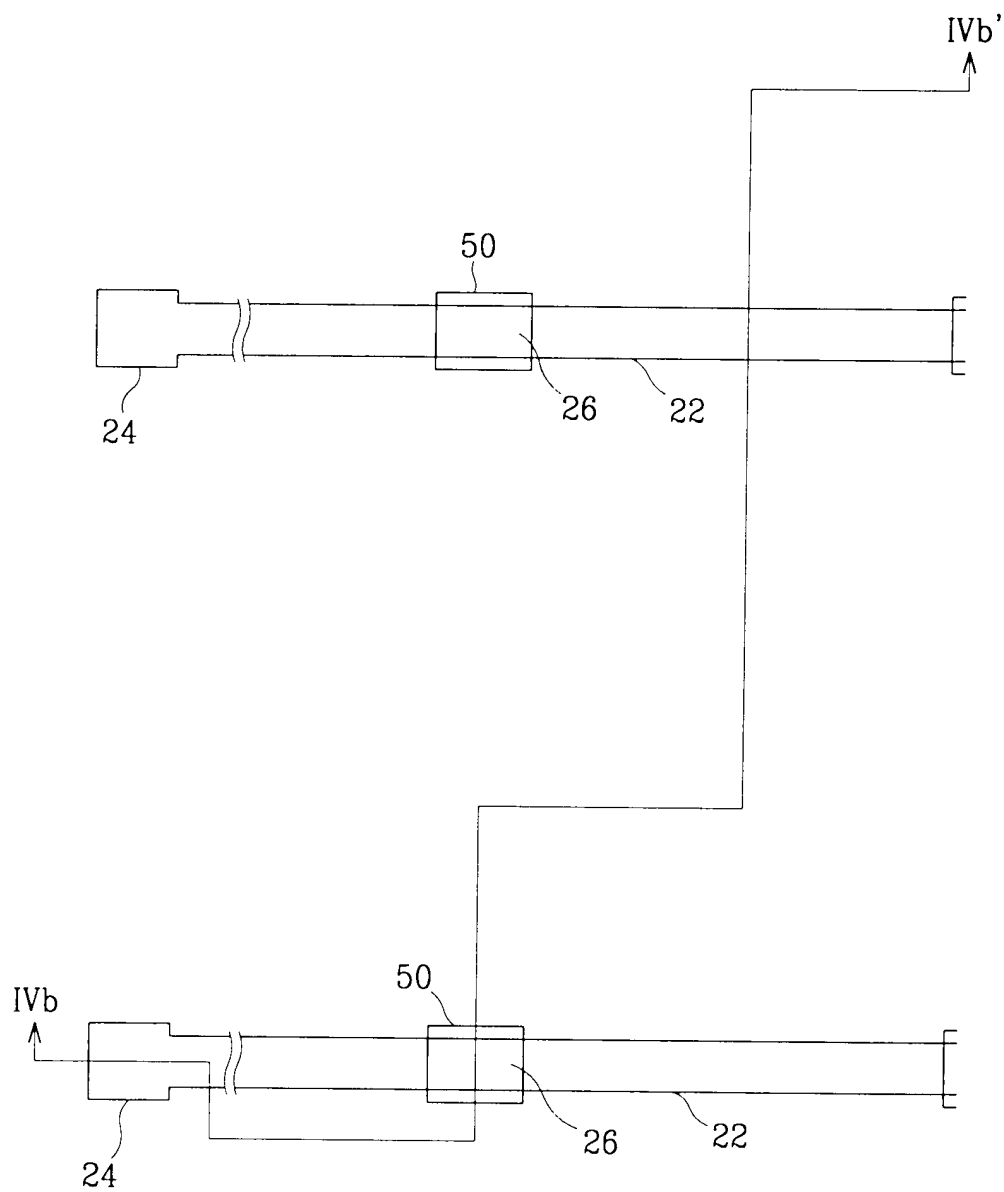
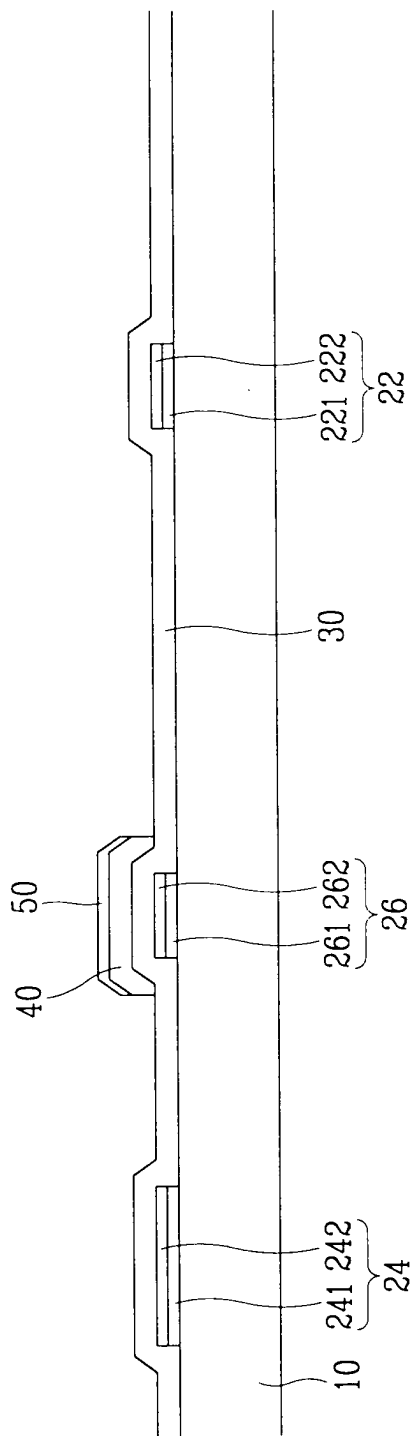


FIG. 4B



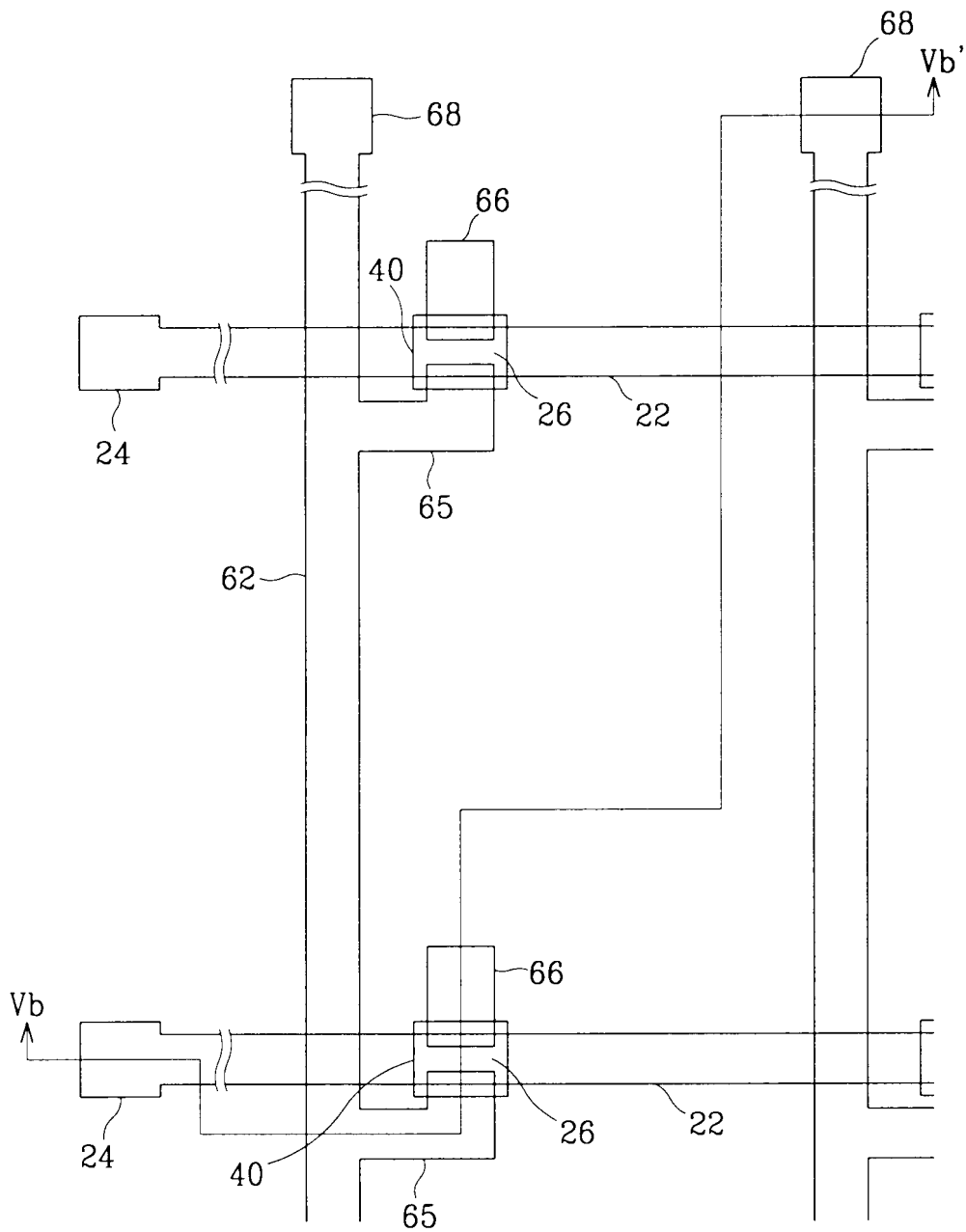


FIG. 5B

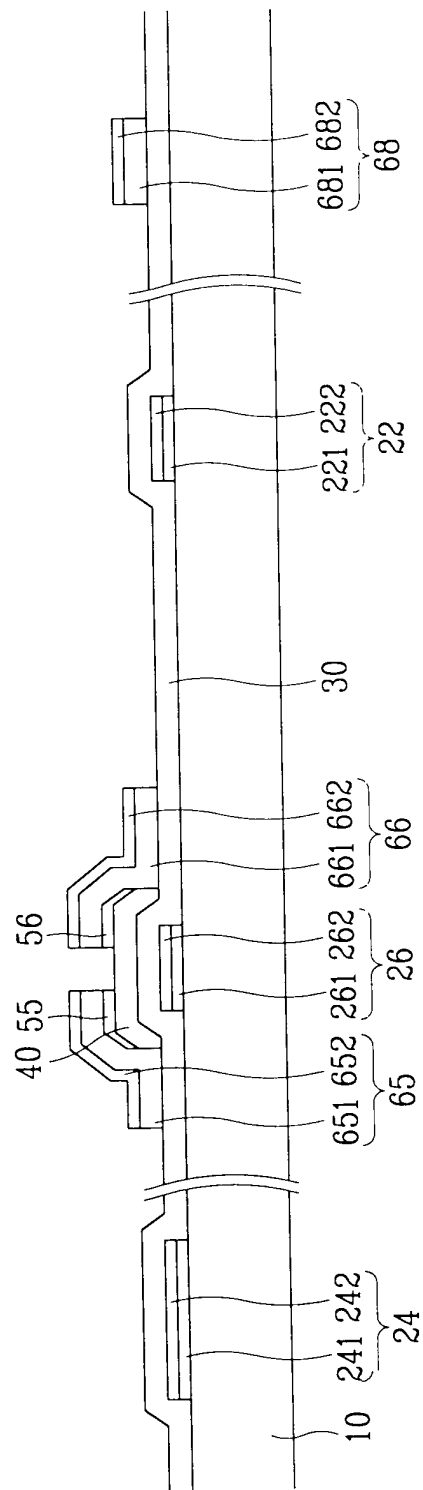




FIG. 6A

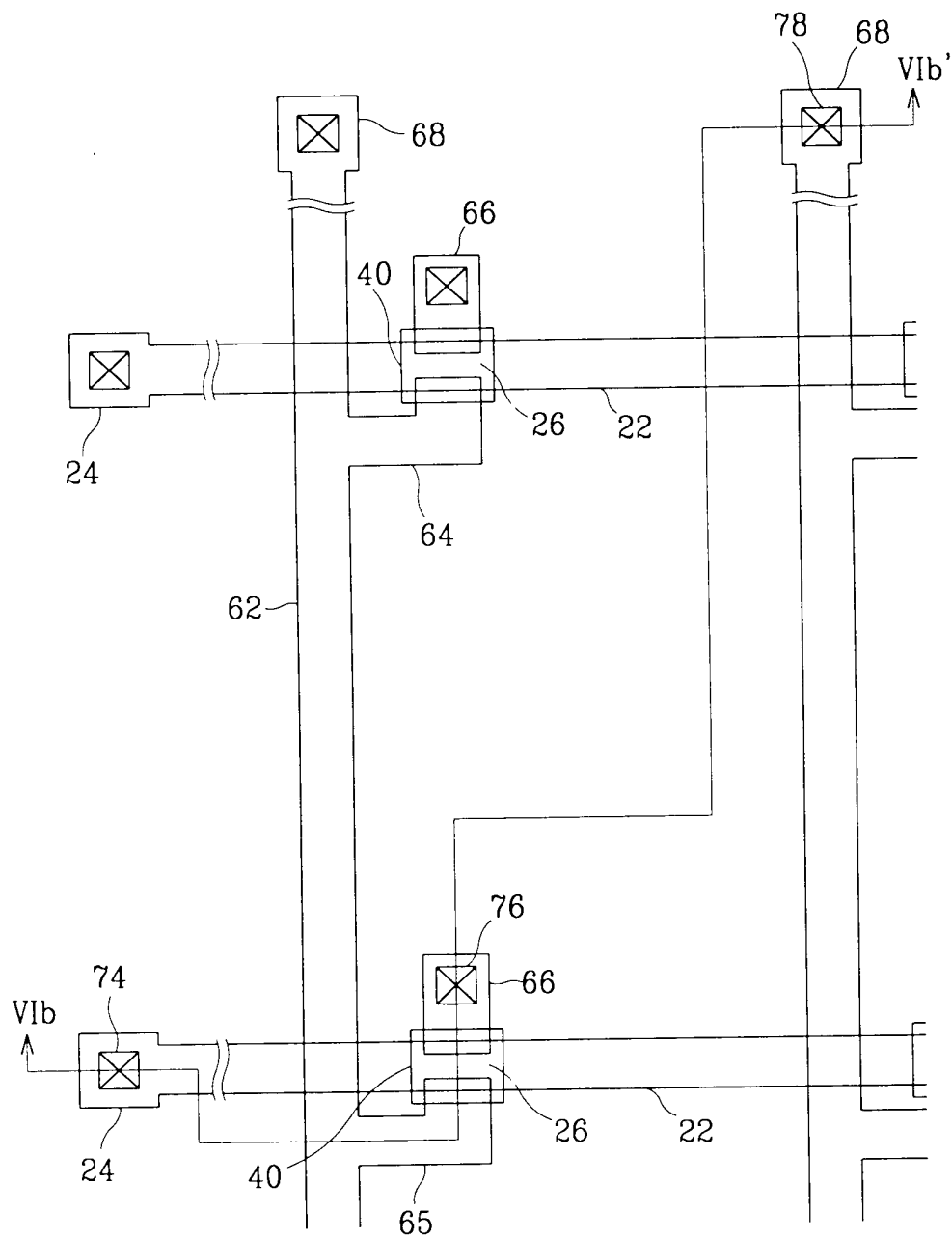


FIG. 6B

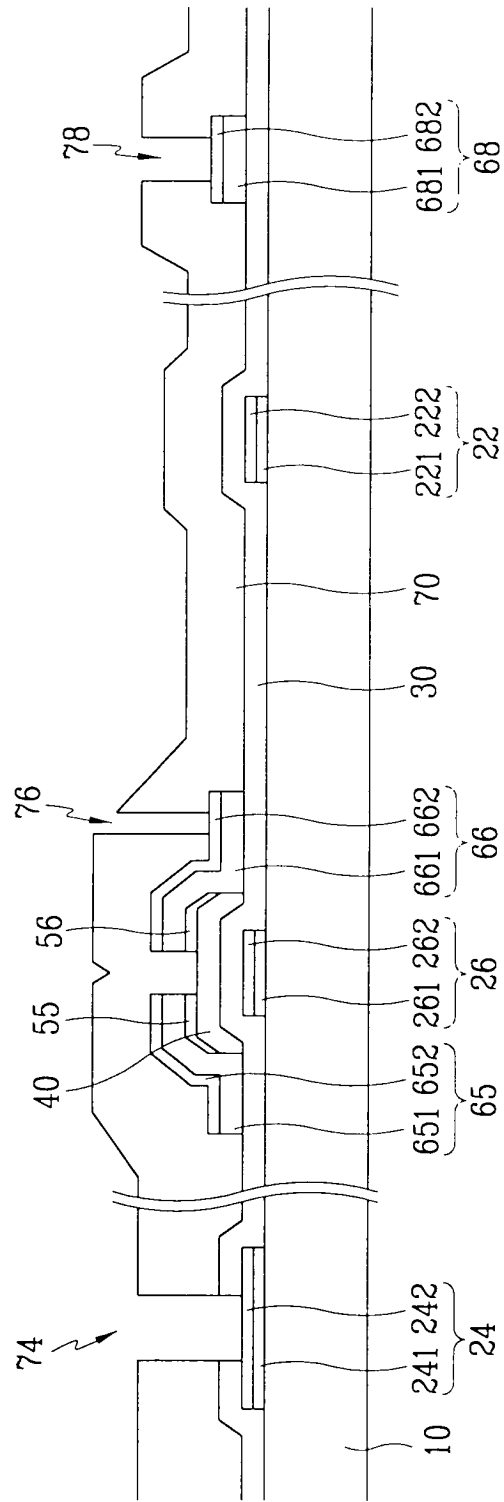


FIG. 7

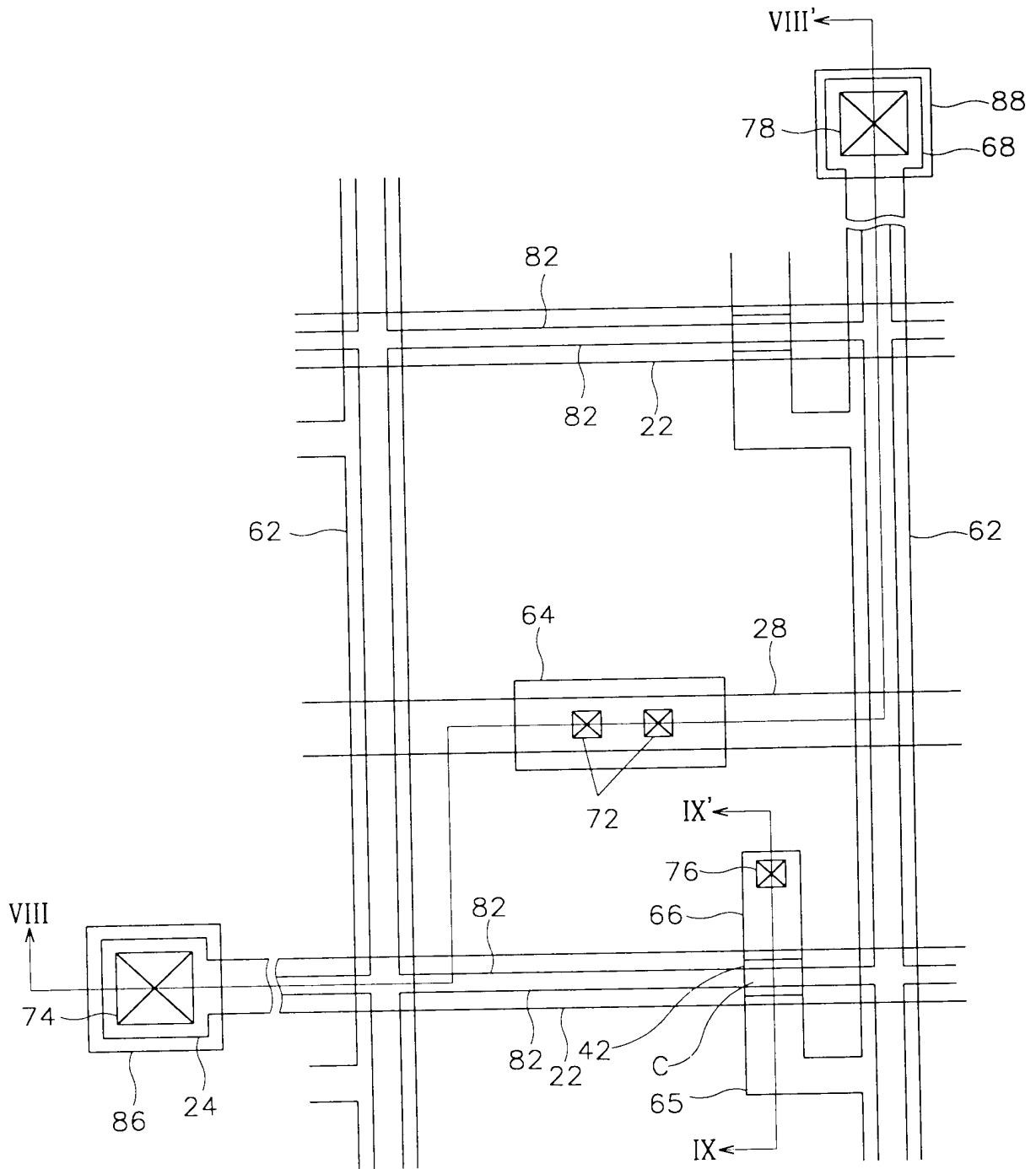


FIG. 8

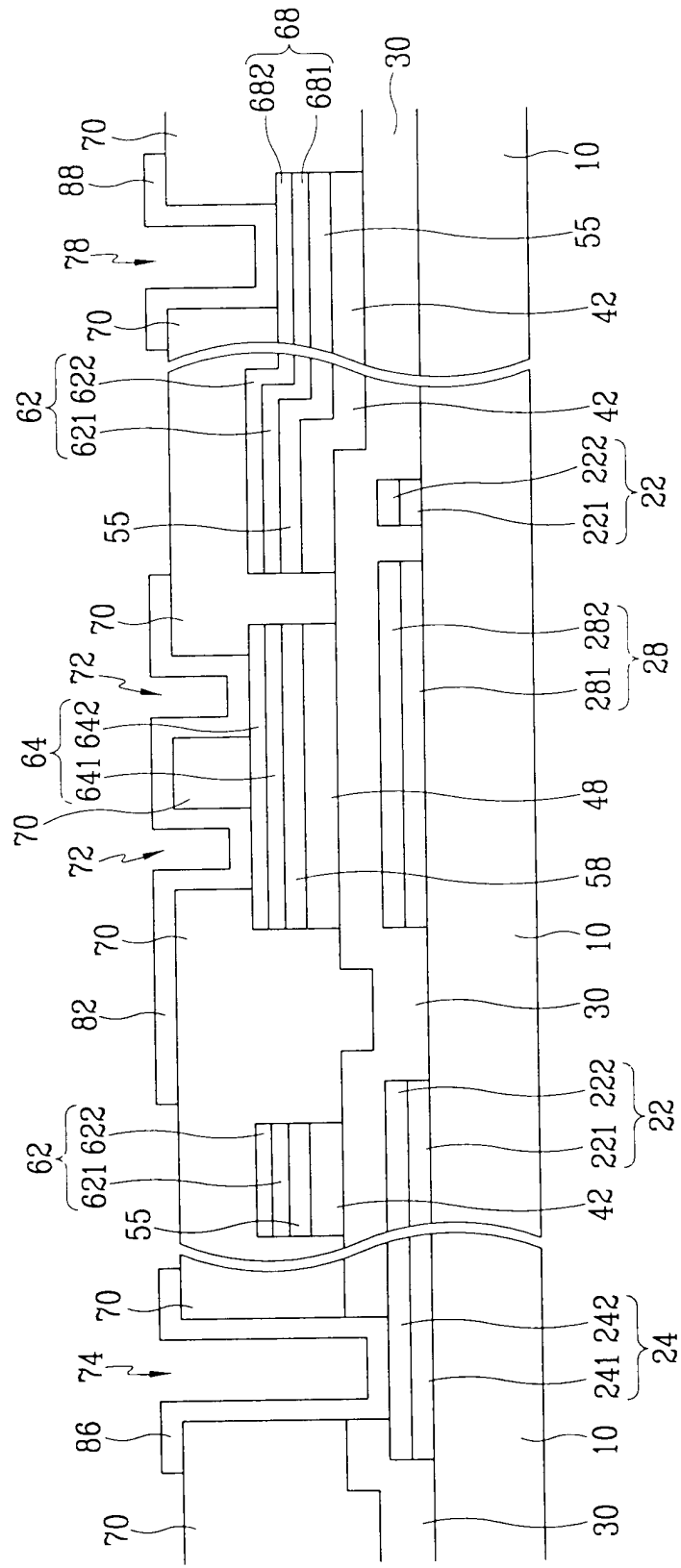


FIG. 9

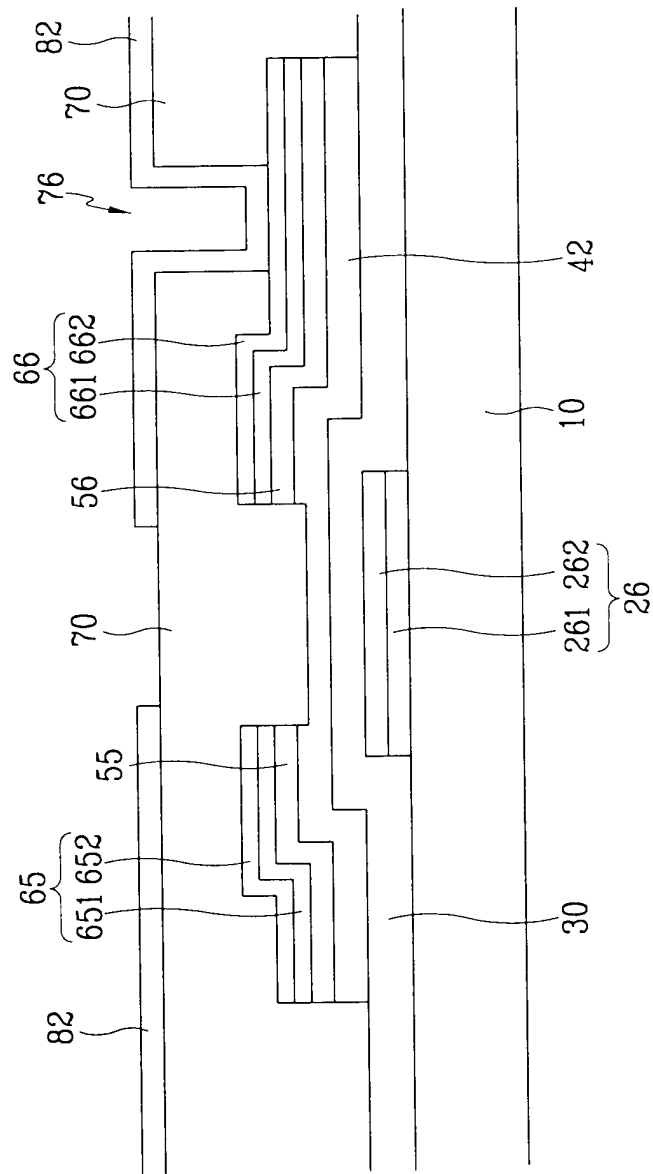


FIG.10A

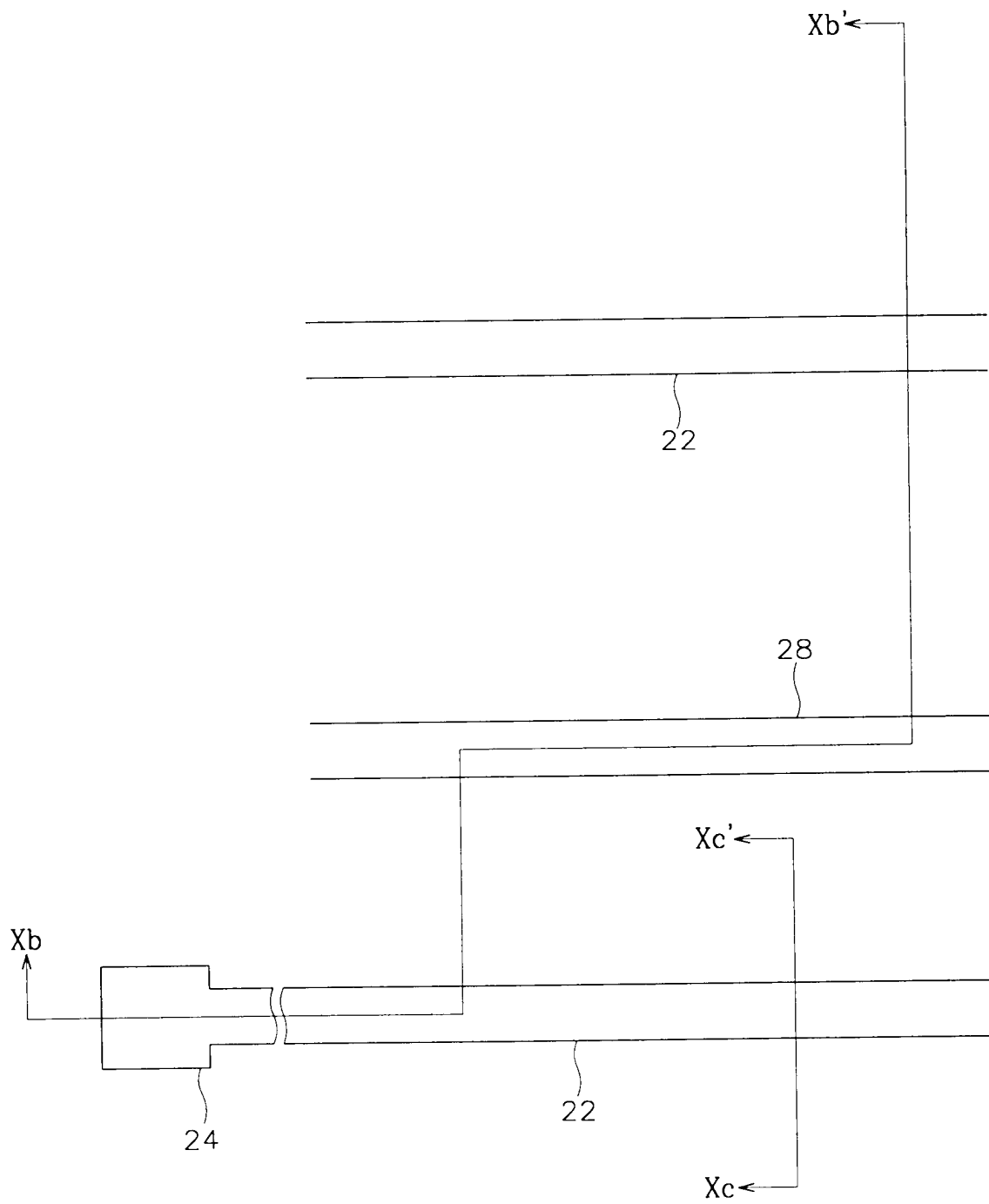


FIG.10B

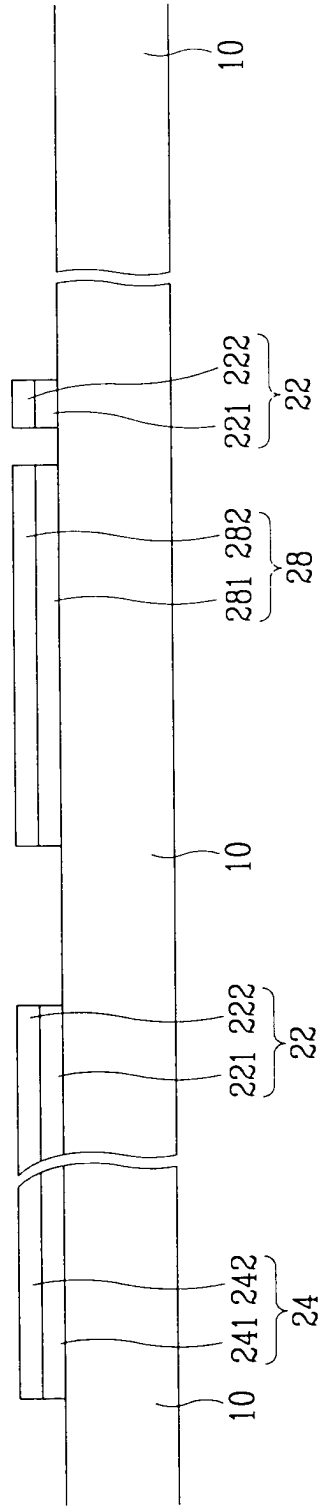


FIG.10C

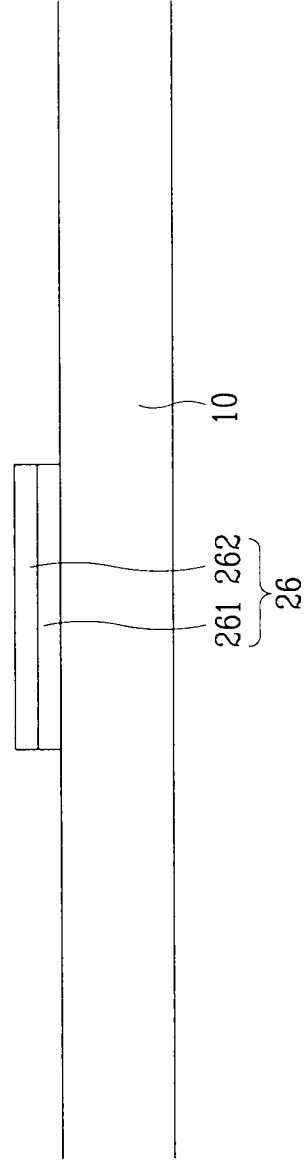






FIG.11B

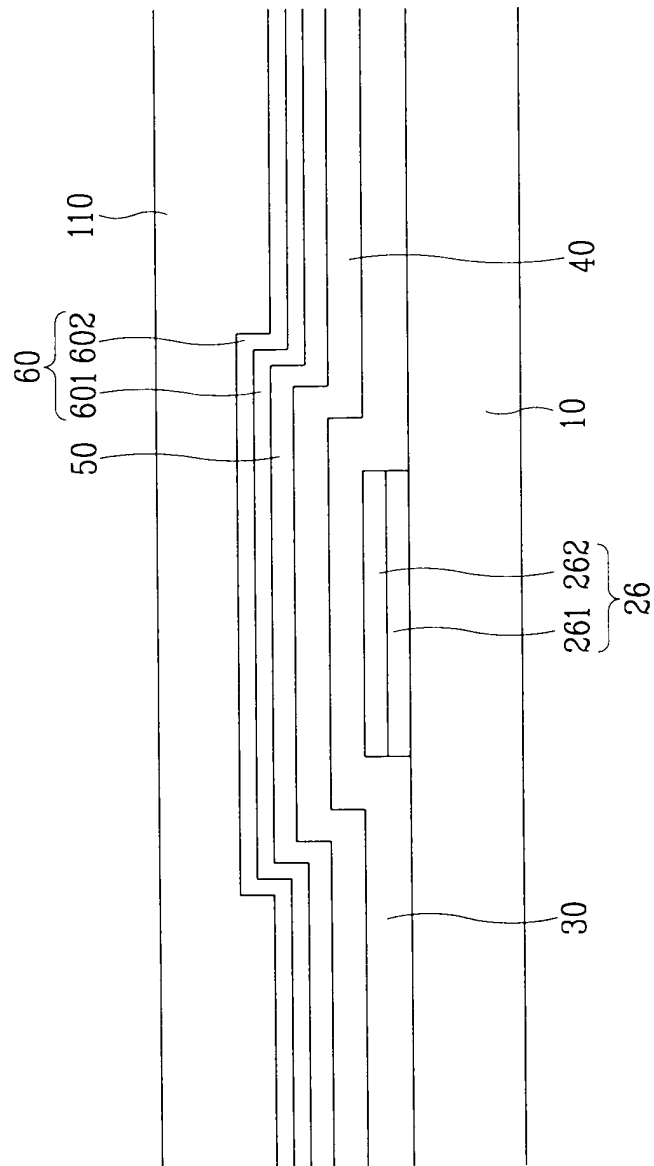


FIG.12A

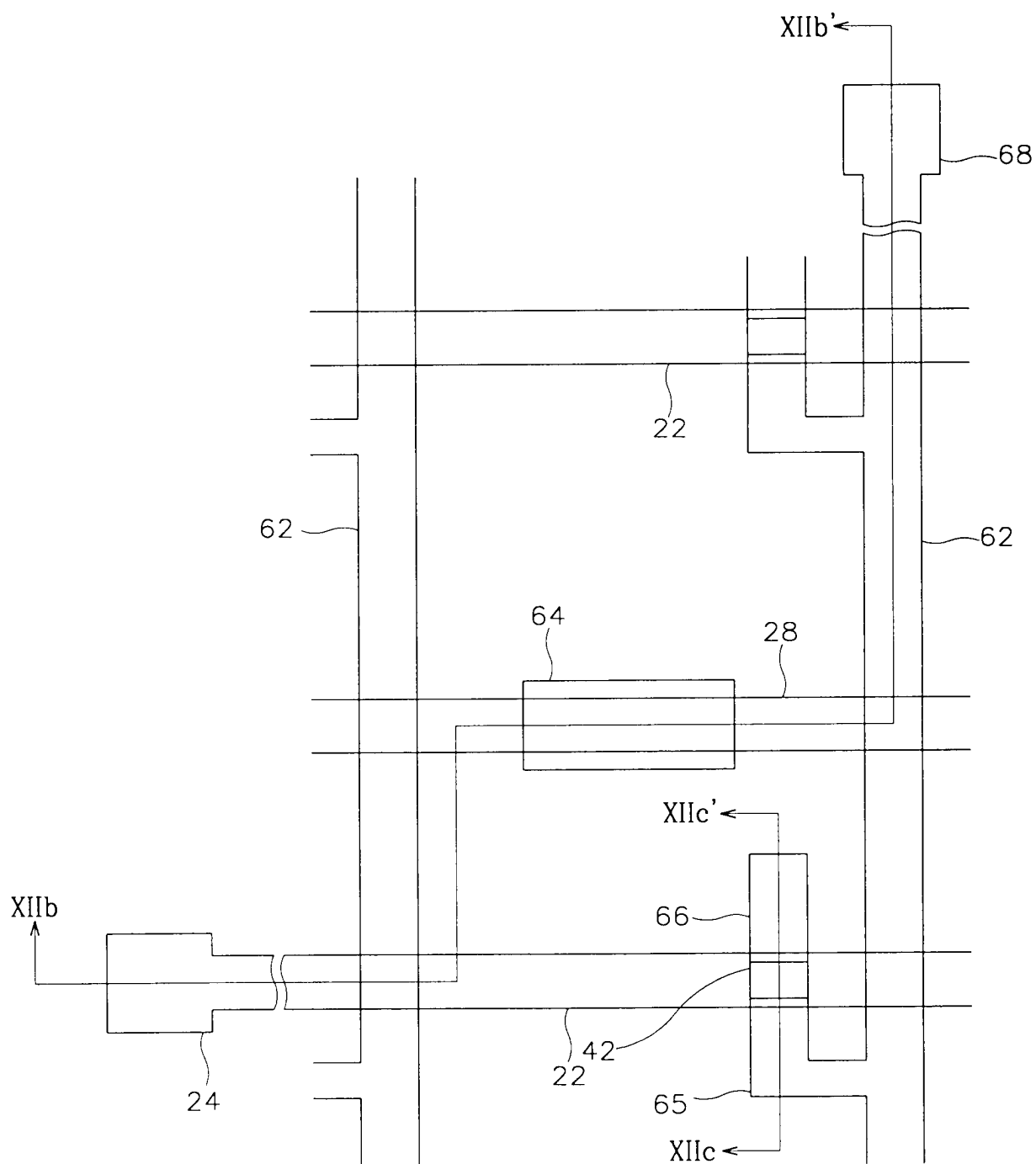


FIG. 12B

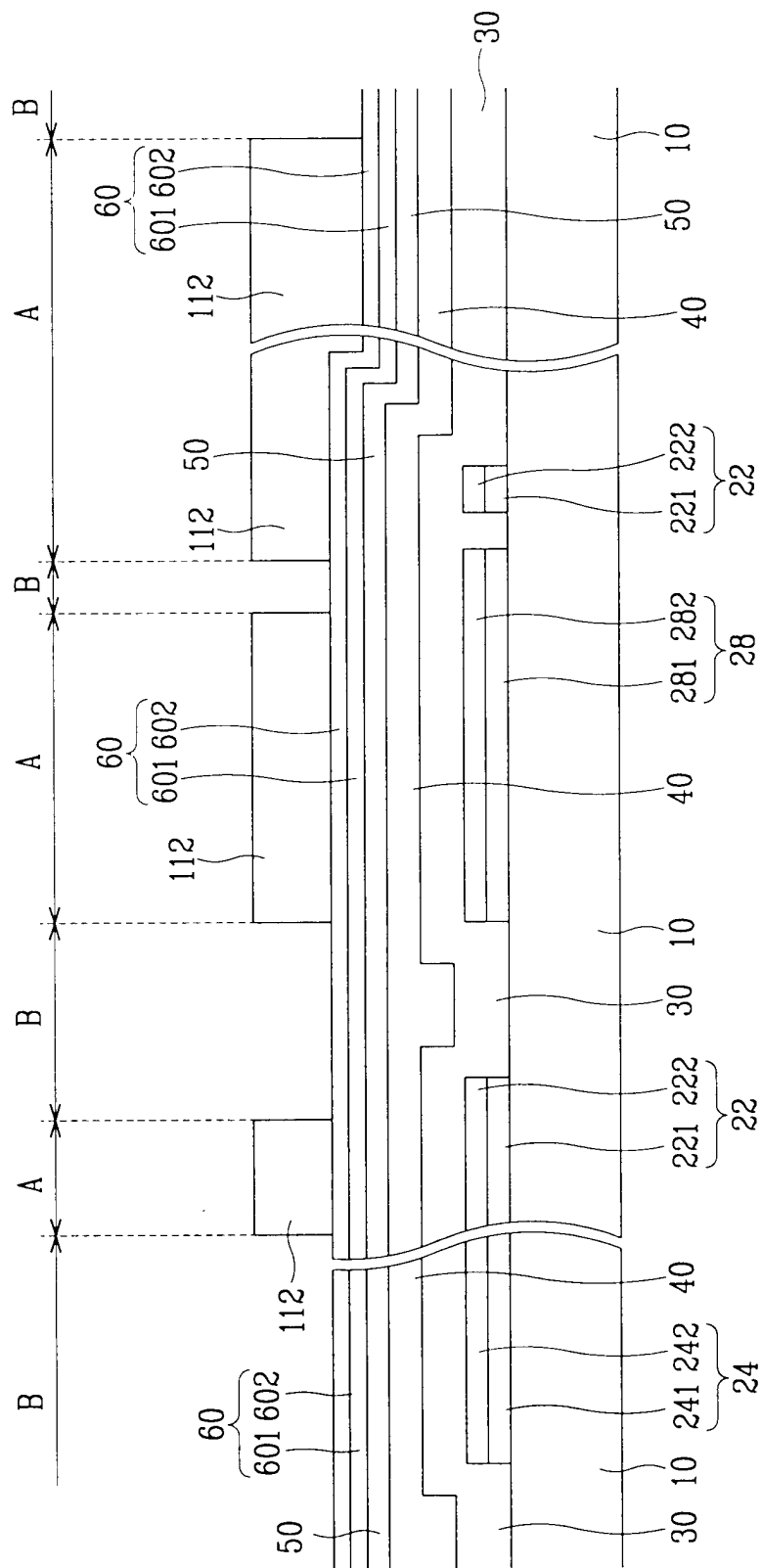


FIG.12C

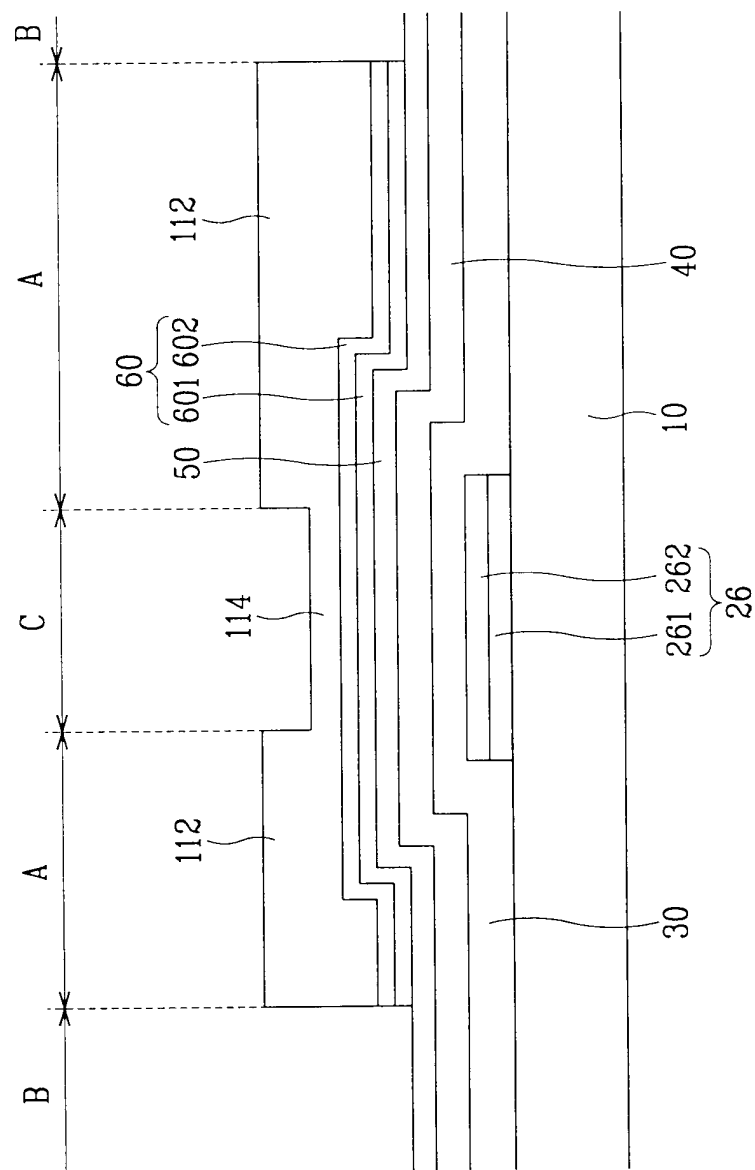


FIG. 13A

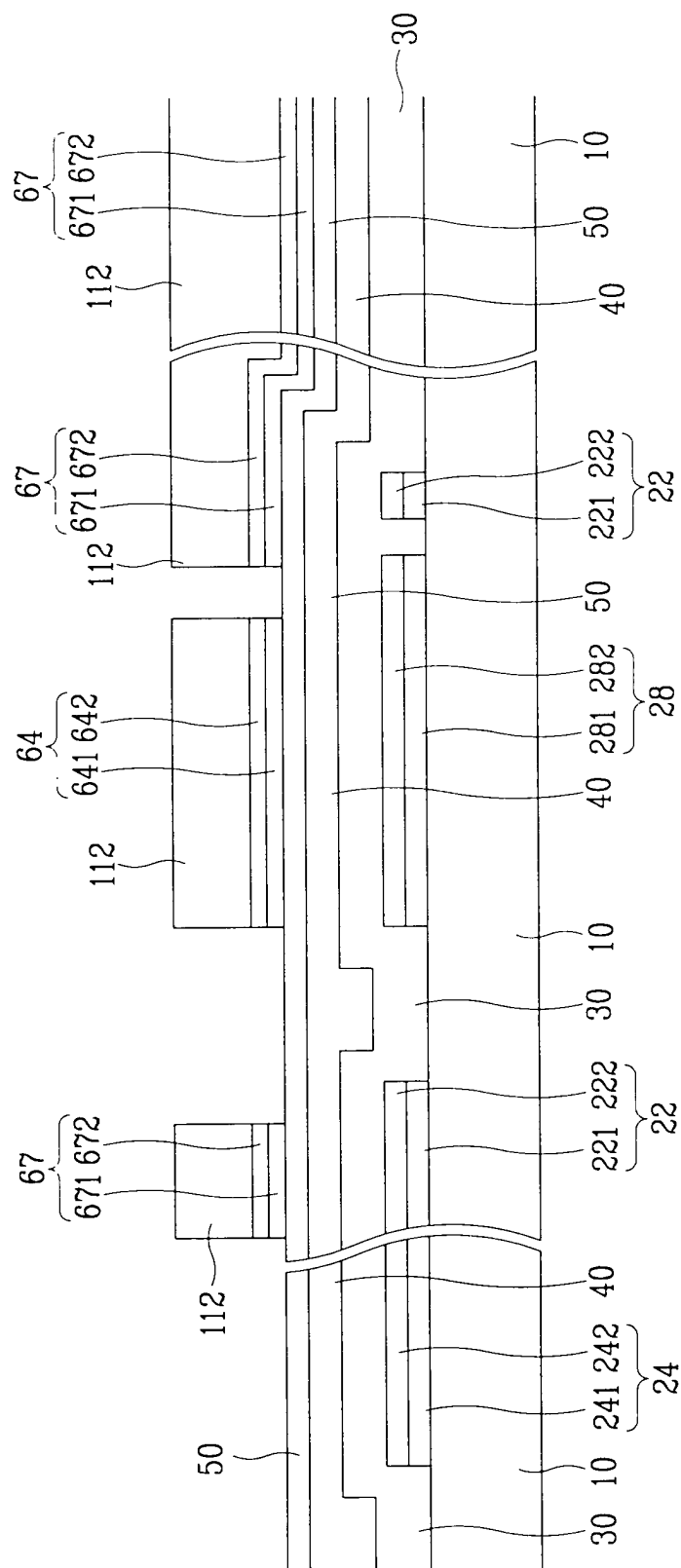


FIG. 13B

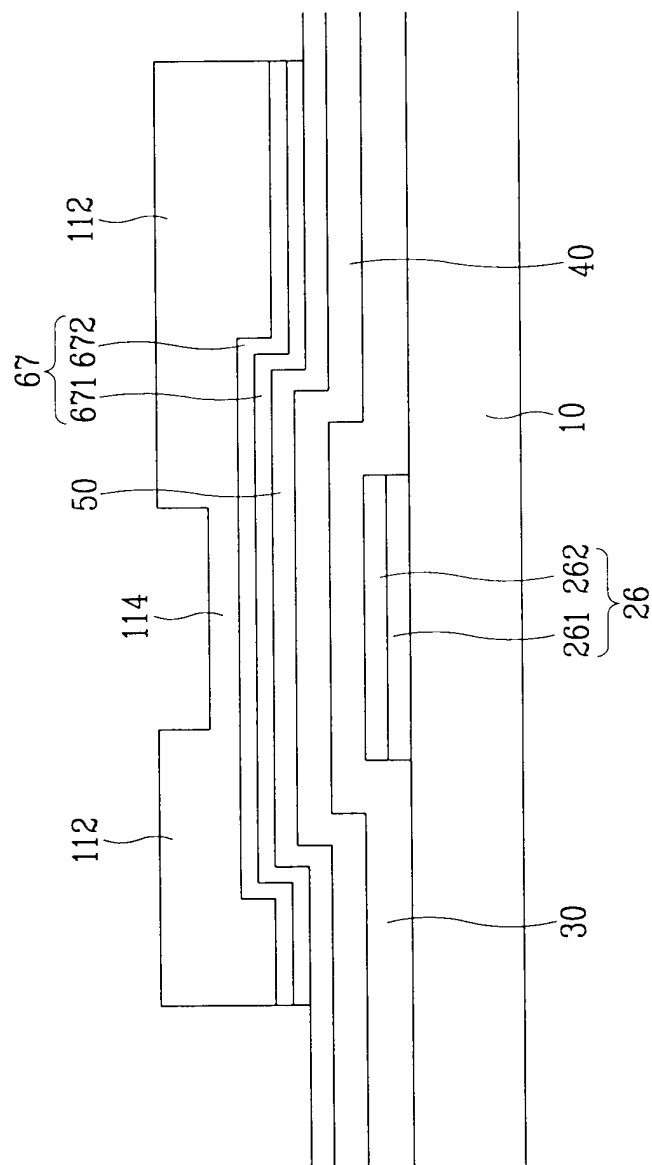


FIG. 14A

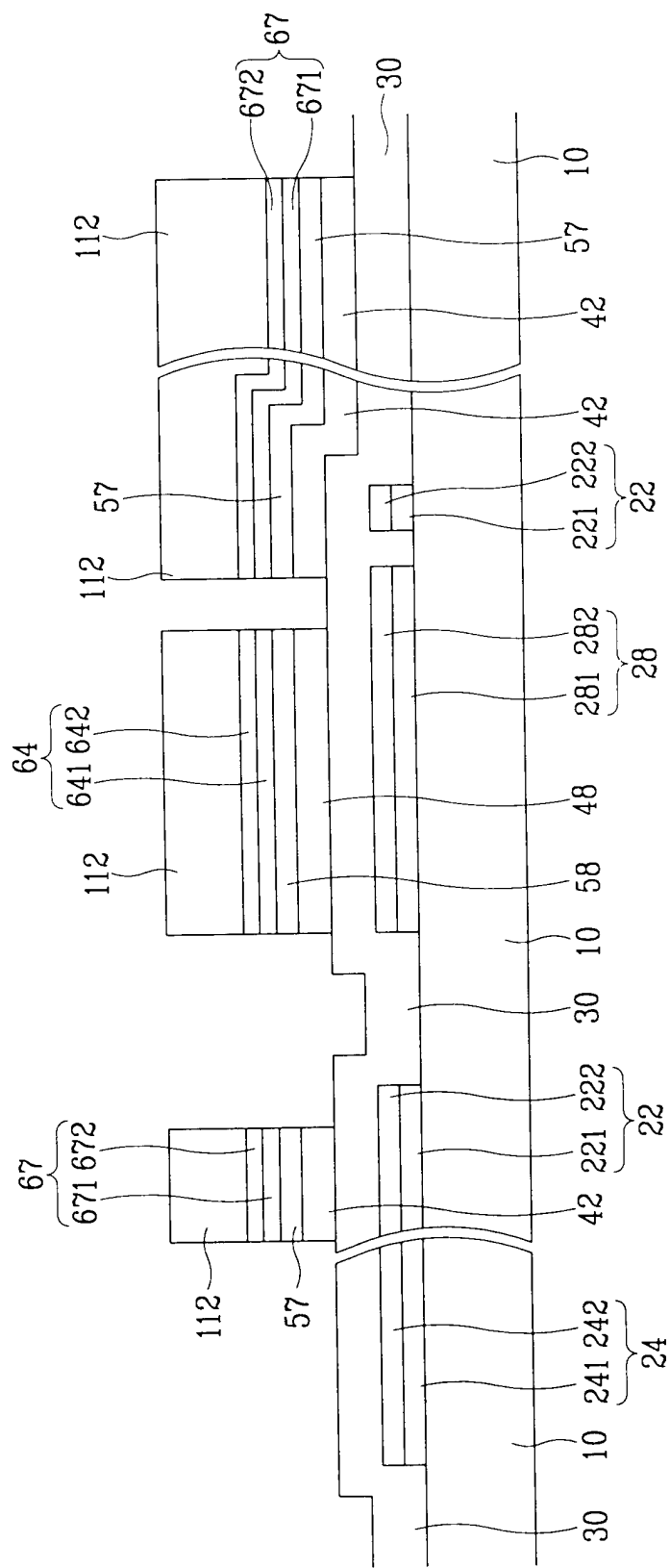




FIG. 14B

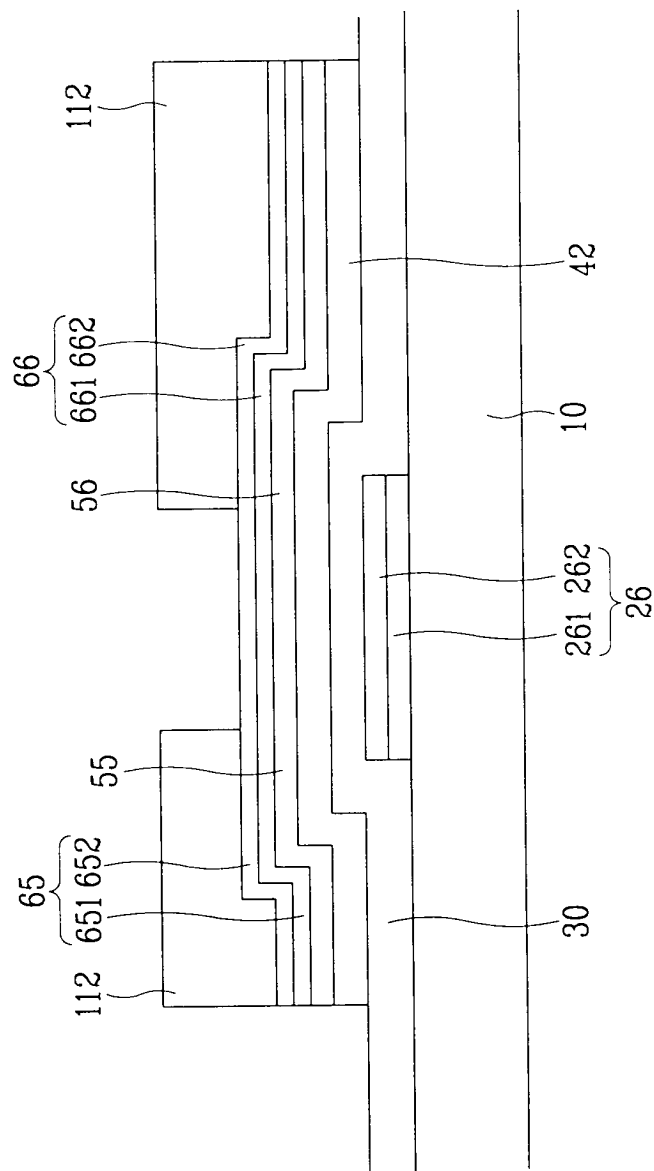


FIG. 15A

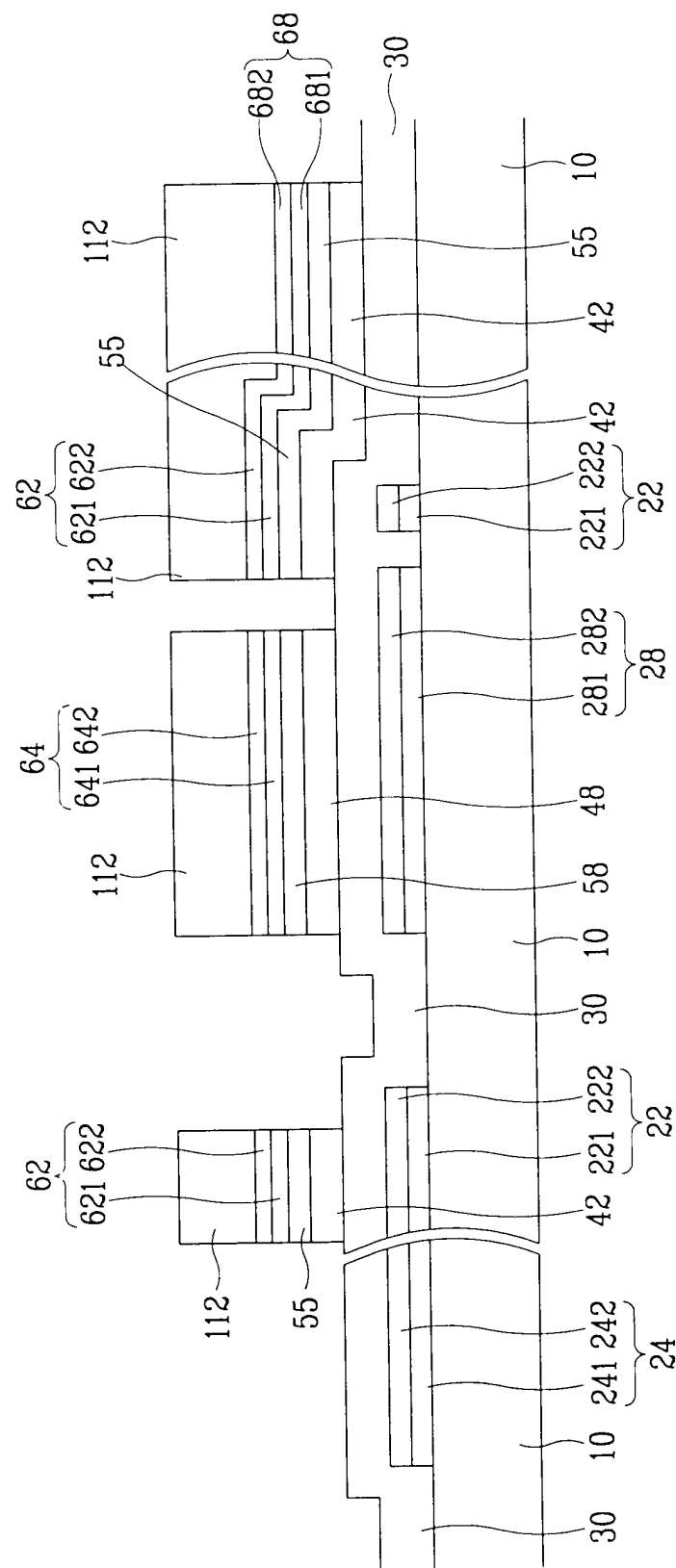
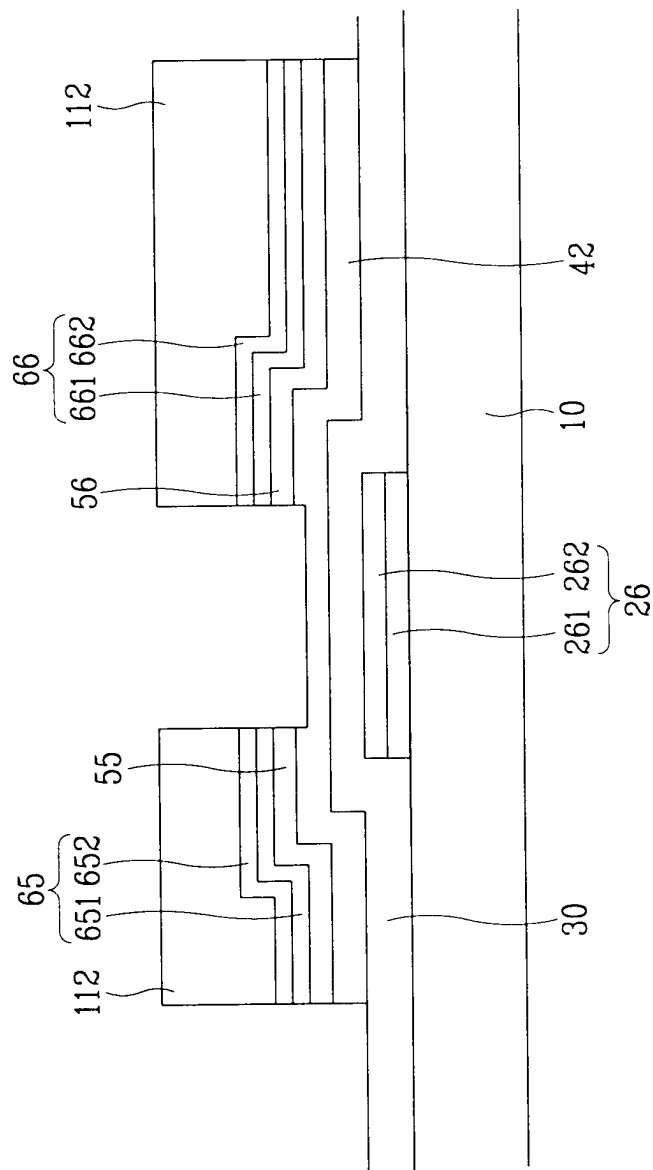


FIG.15B



This diagram shows a cross-sectional view of a semiconductor device. It features a substrate with multiple layers and regions. Key components include:

- Substrate (10):** The base layer of the device.
- Regions (20, 22, 24, 28):** Various functional areas defined by different materials or structures.
- Layers (221, 222, 281, 282, 42, 48, 55, 56, 58, 621, 622, 641, 642, 681, 682):** Individual thin films or coatings within the device.
- Structures (30, 32, 34, 36, 38, 40, 44, 46, 48, 50, 52, 54, 56, 58, 60, 62, 64, 66, 68):** Specific features or components that may be part of a larger assembly.
- Interconnects (70):** Conductive paths that connect different parts of the device.

The diagram illustrates the complex layering and structural arrangement typical of modern semiconductor technology.

FIG. 16B

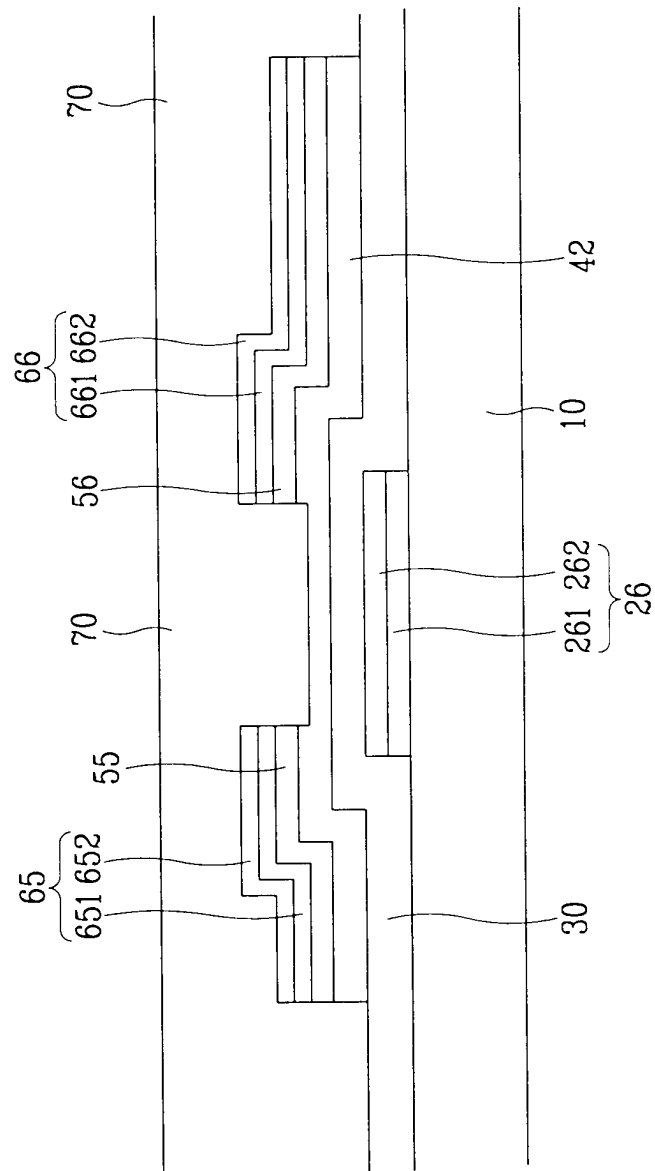


FIG.17A

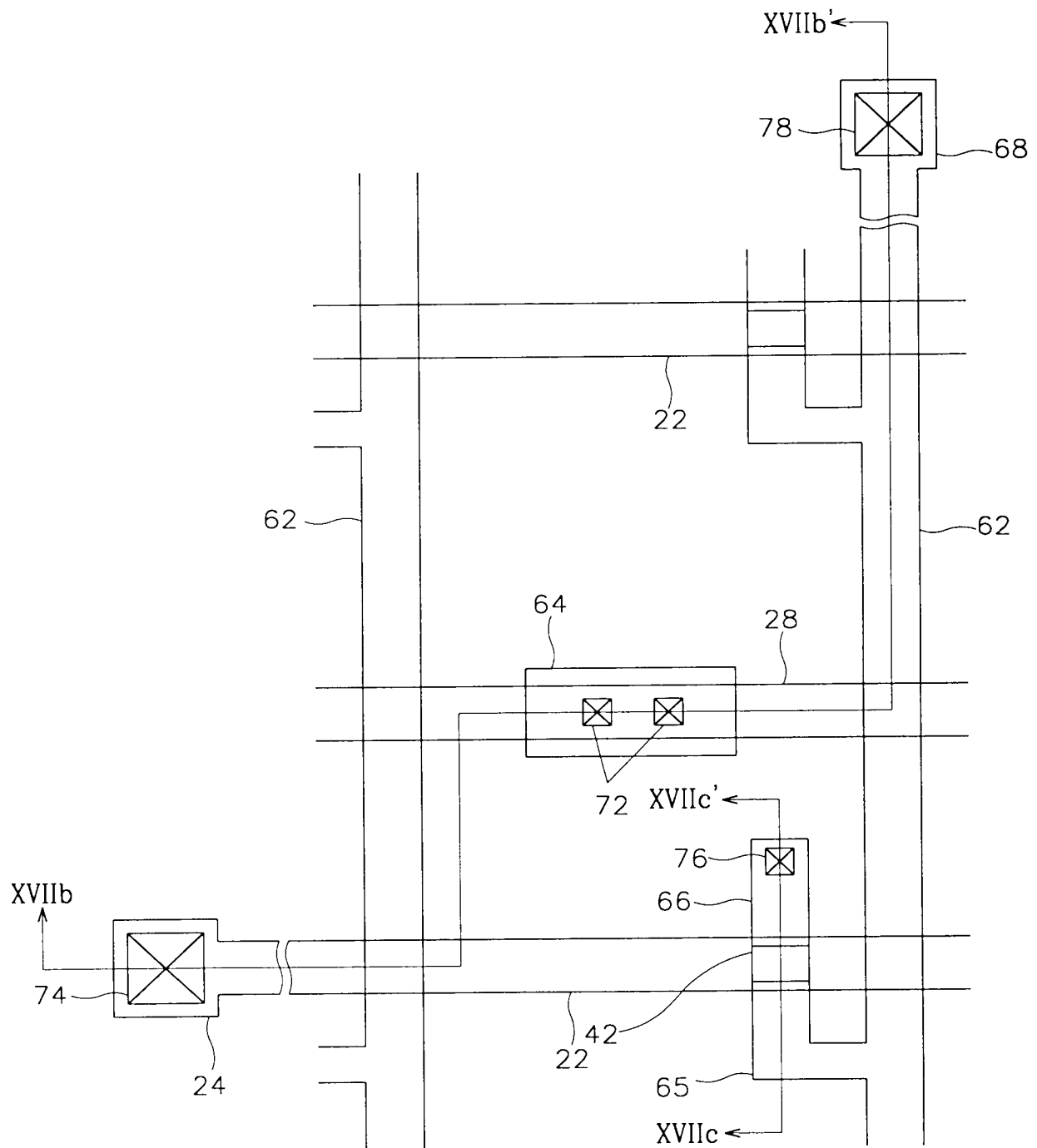
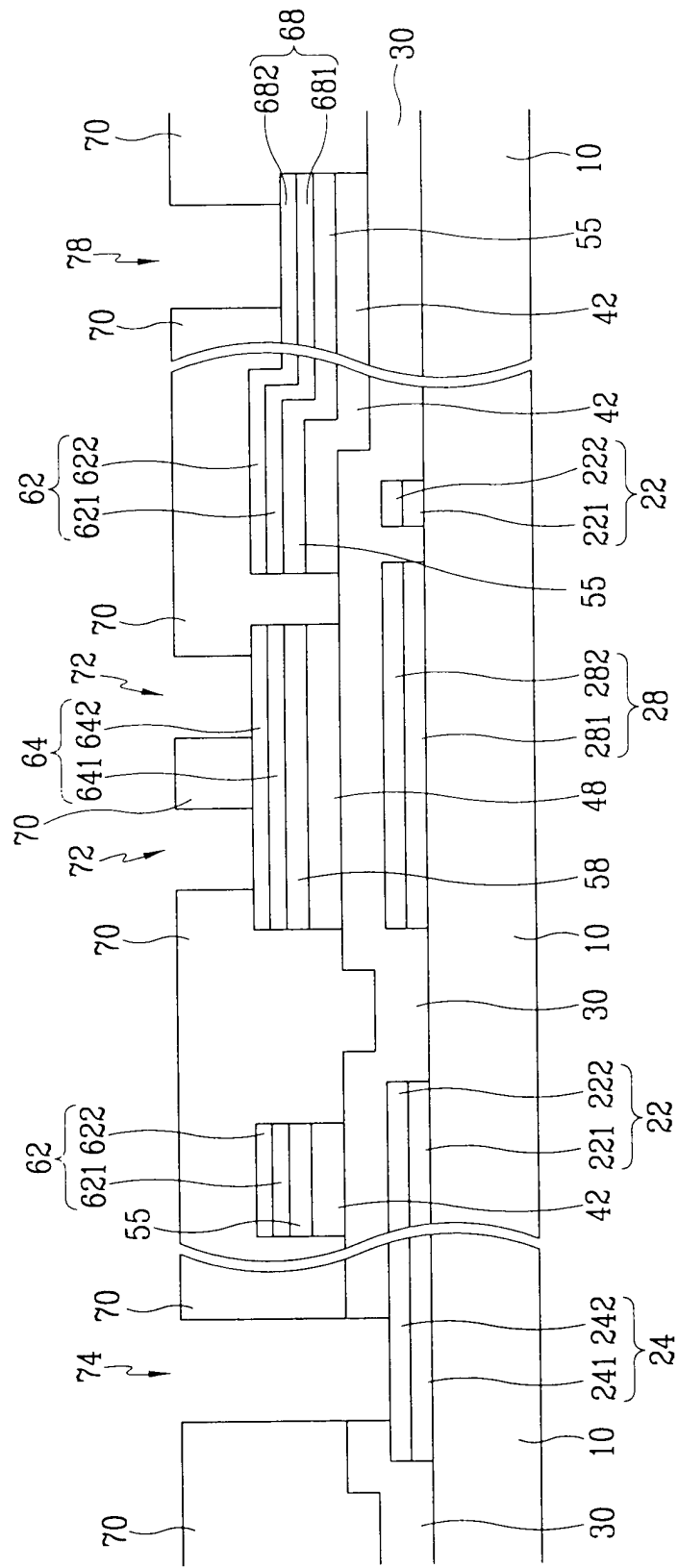


FIG. 17B



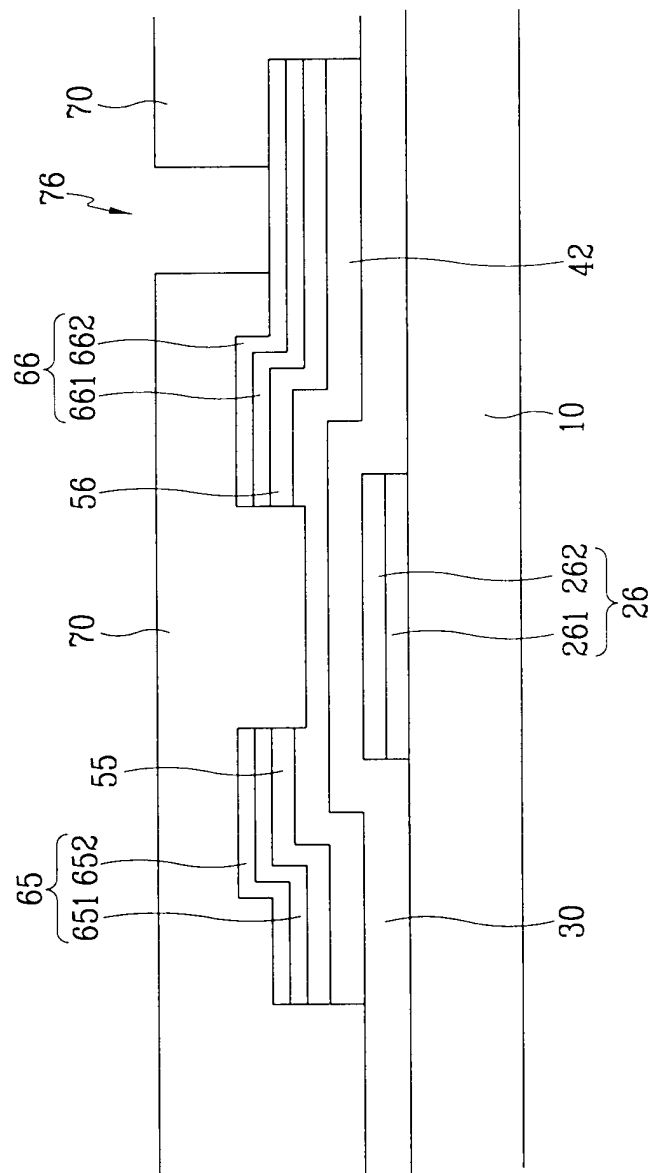




FIG.18

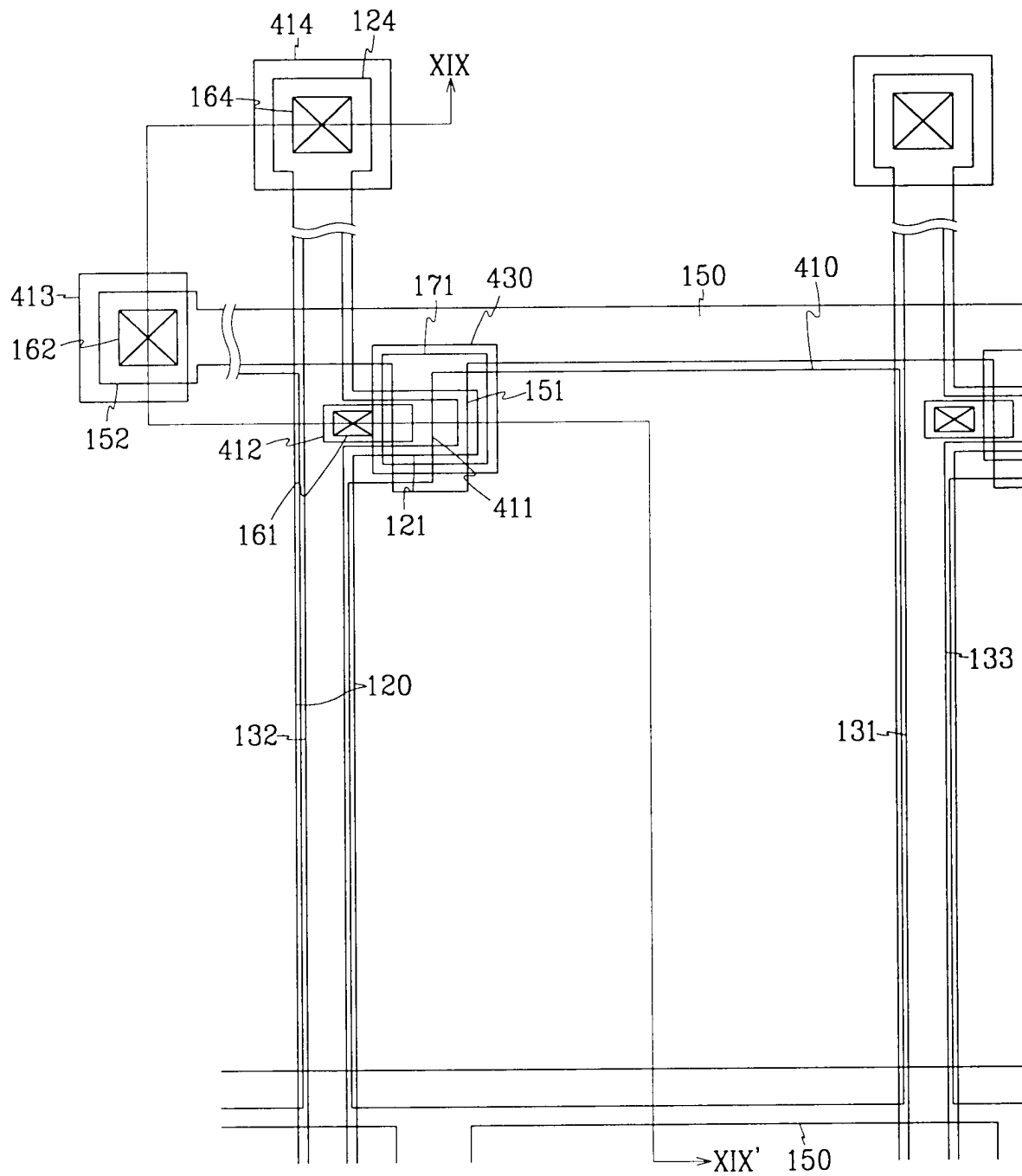


FIG.19

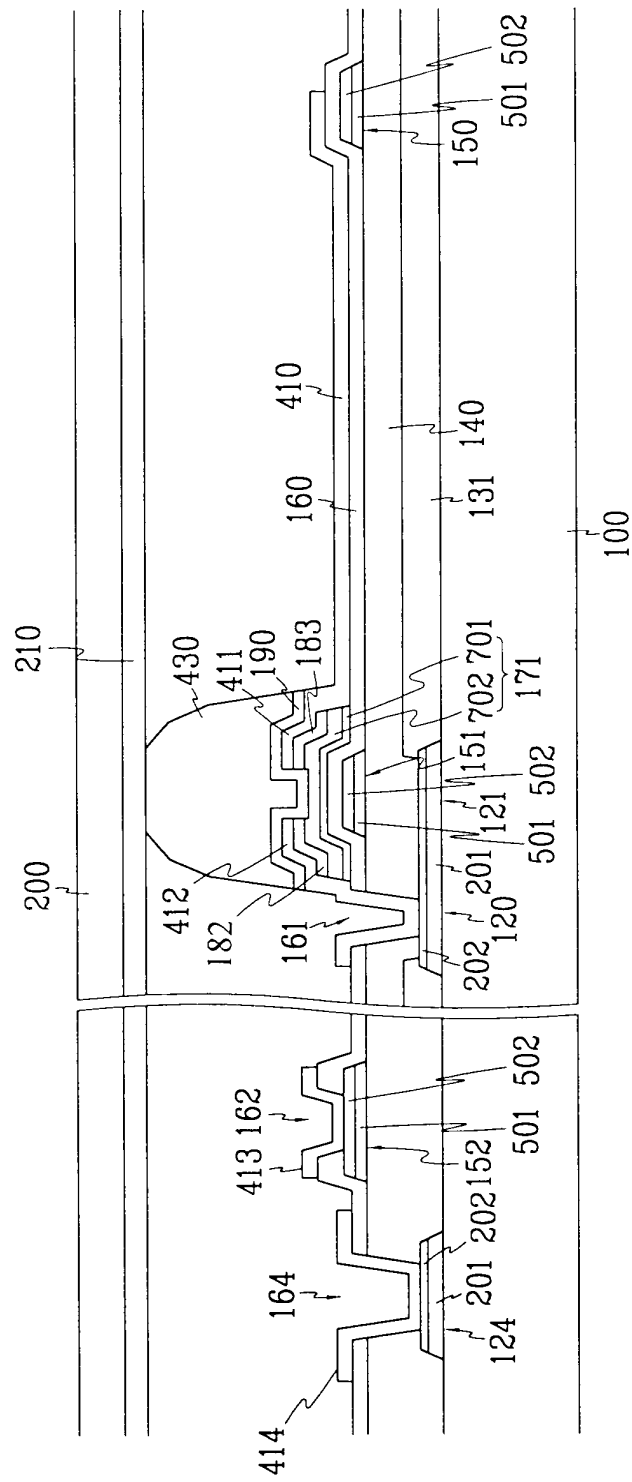


FIG.20A

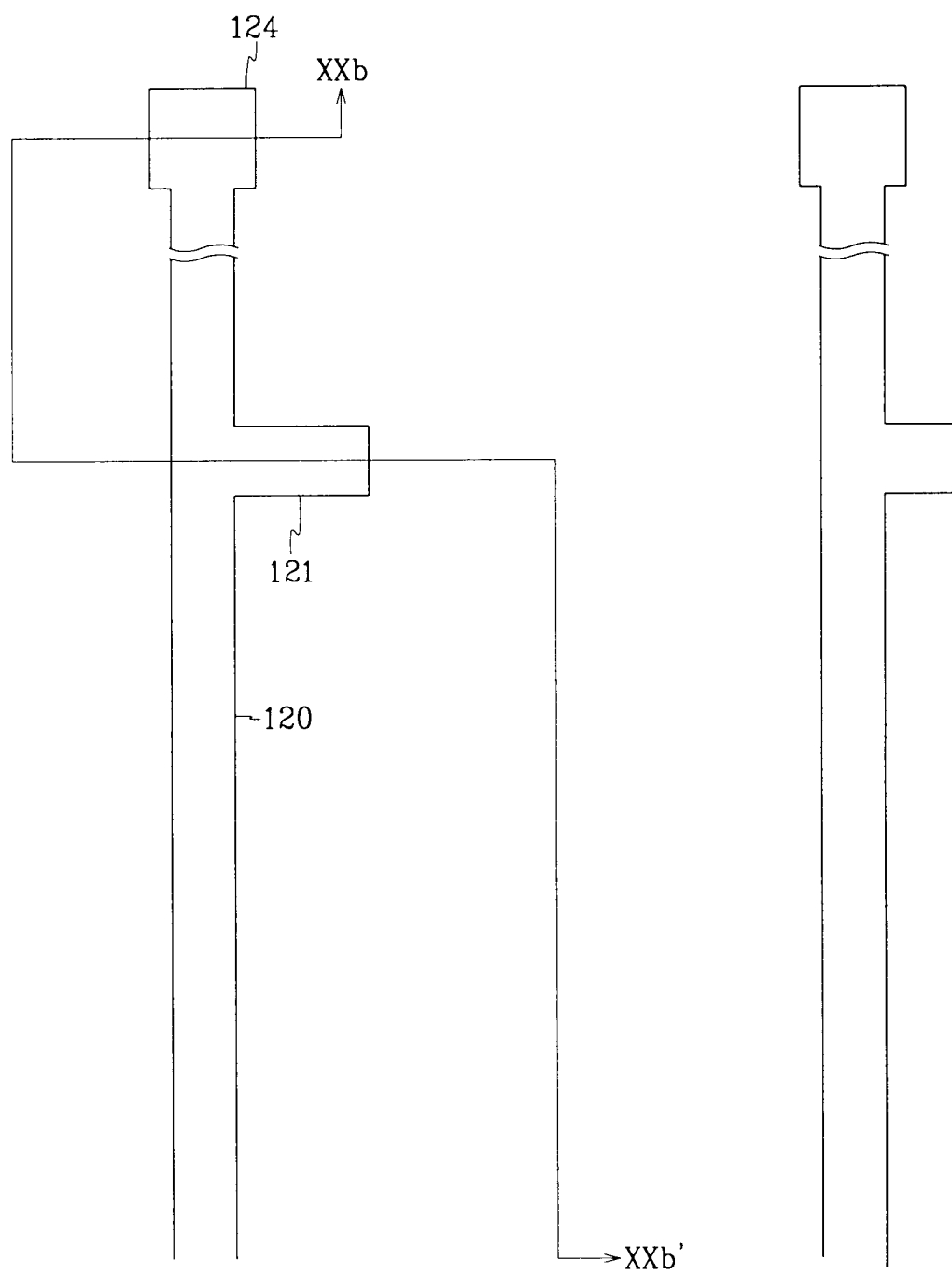


FIG. 20B

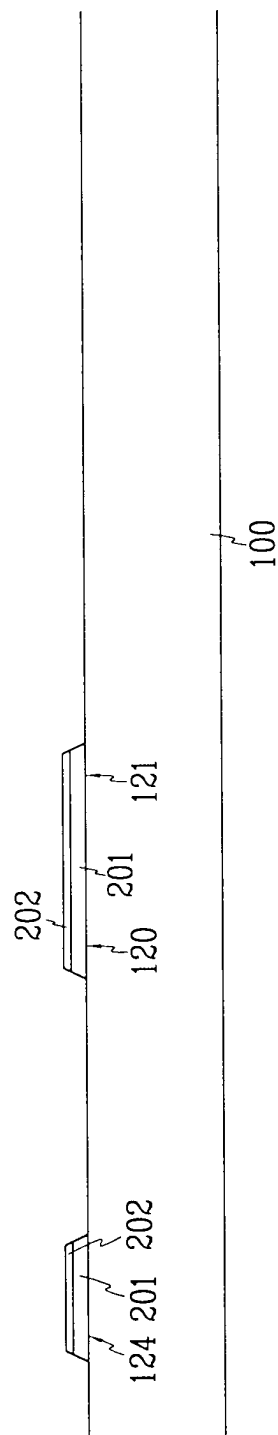


FIG.21A

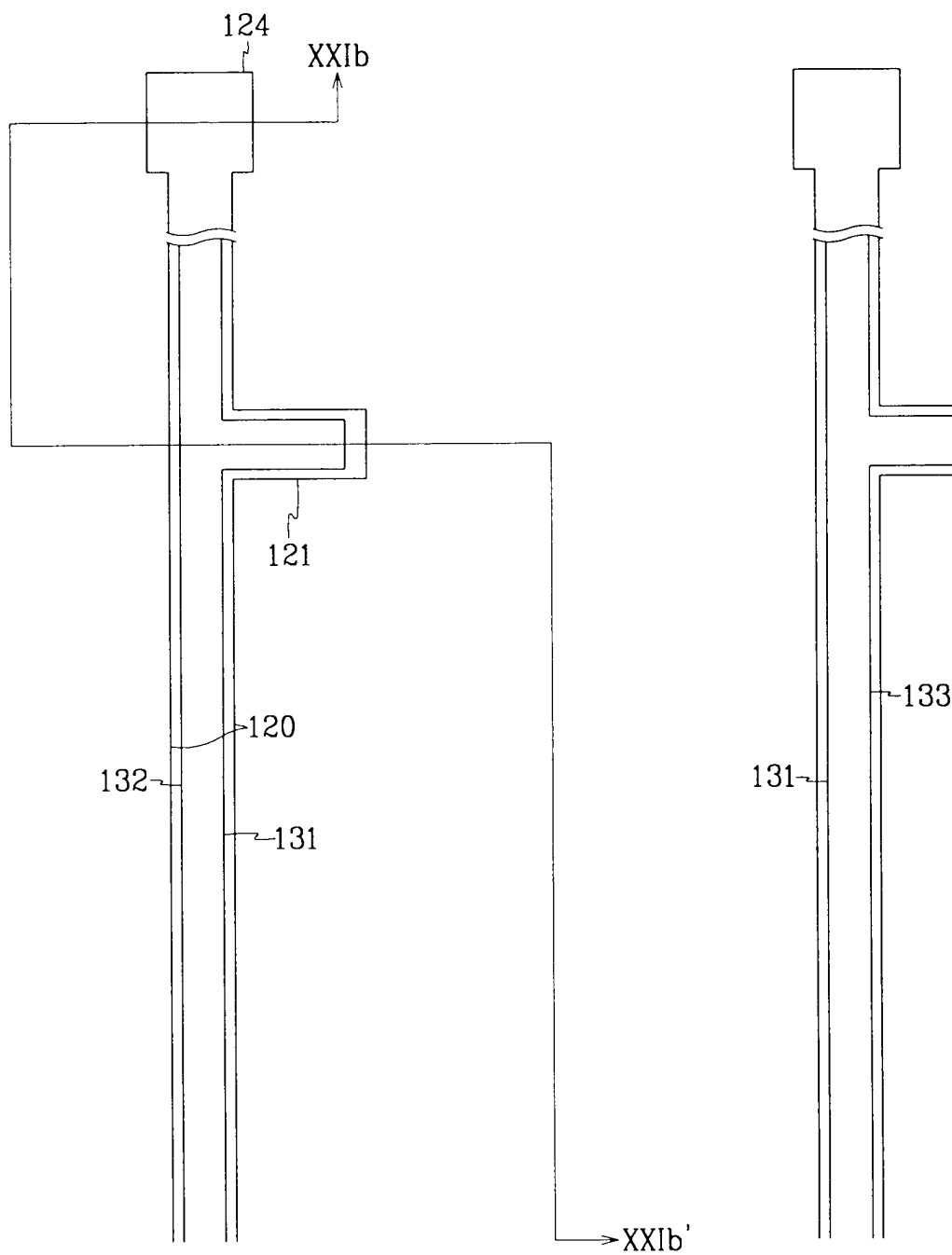


FIG. 21B

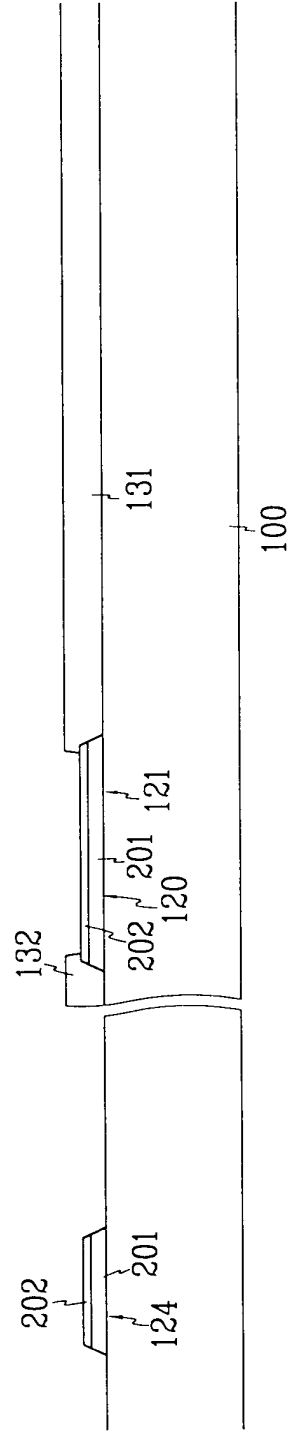


FIG.22A

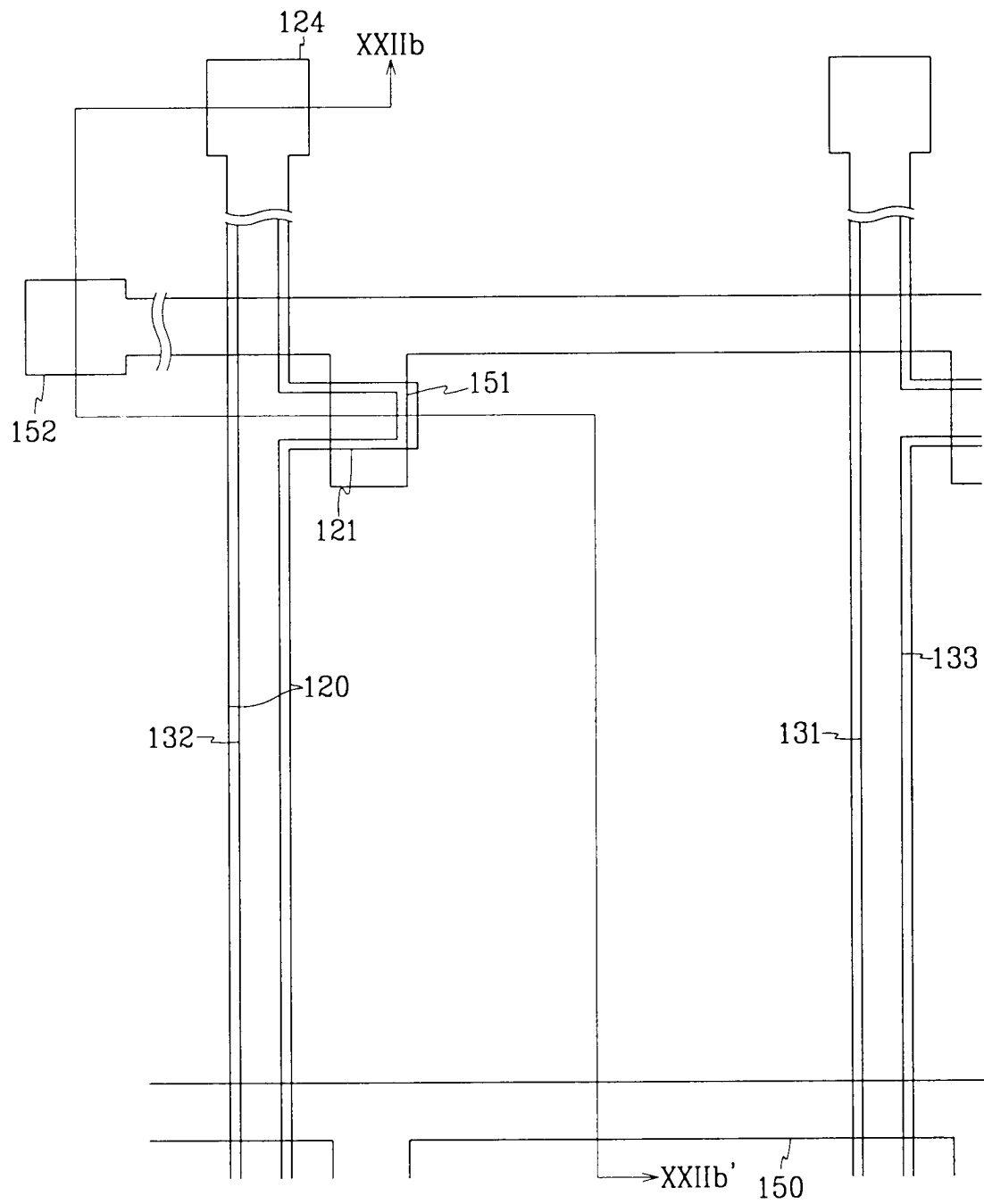


FIG. 22B

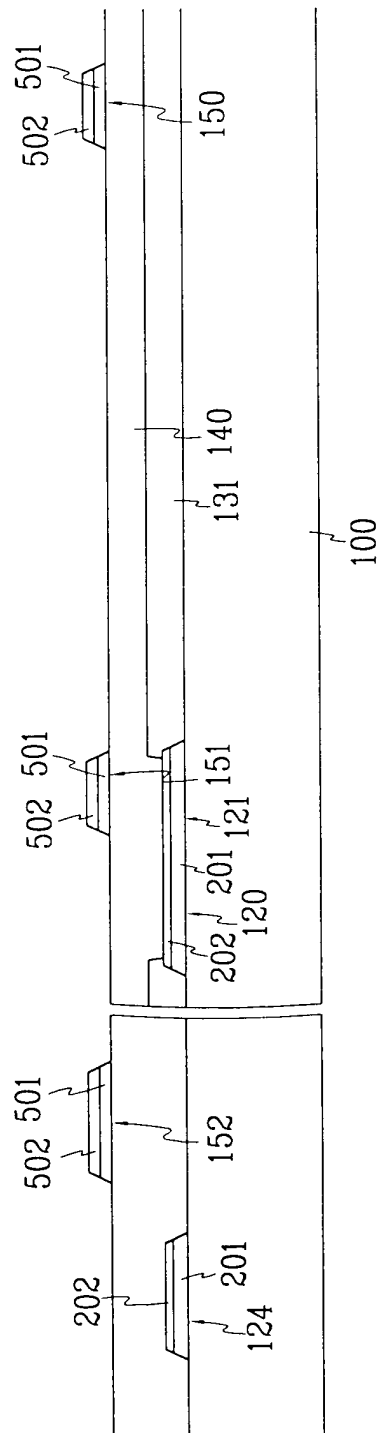




FIG. 23

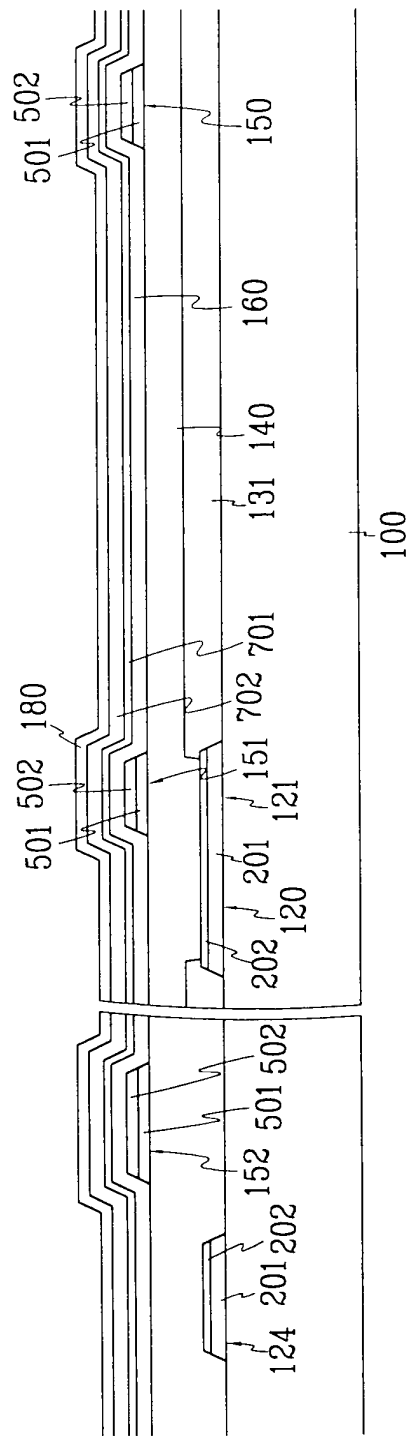
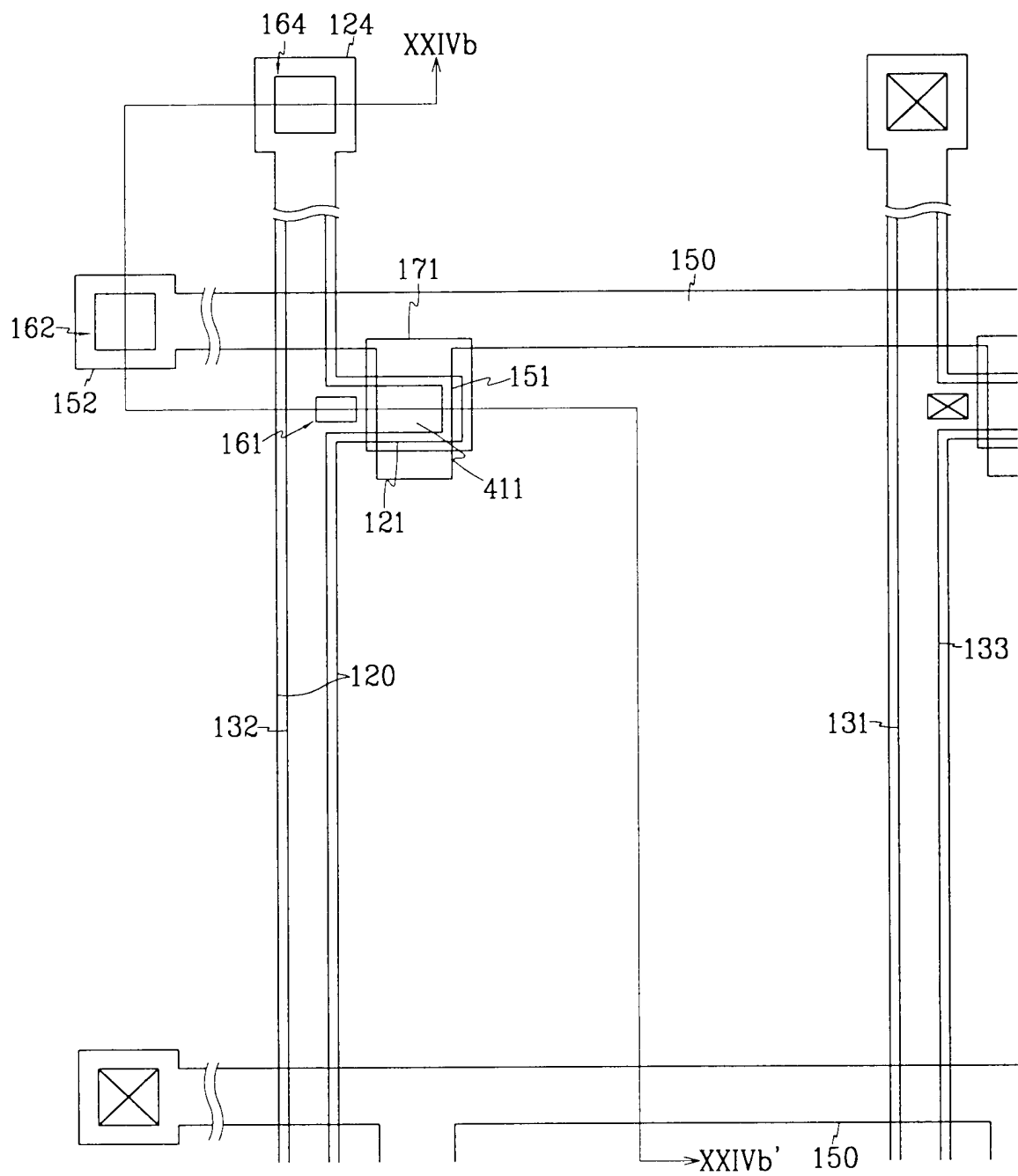


FIG.24A



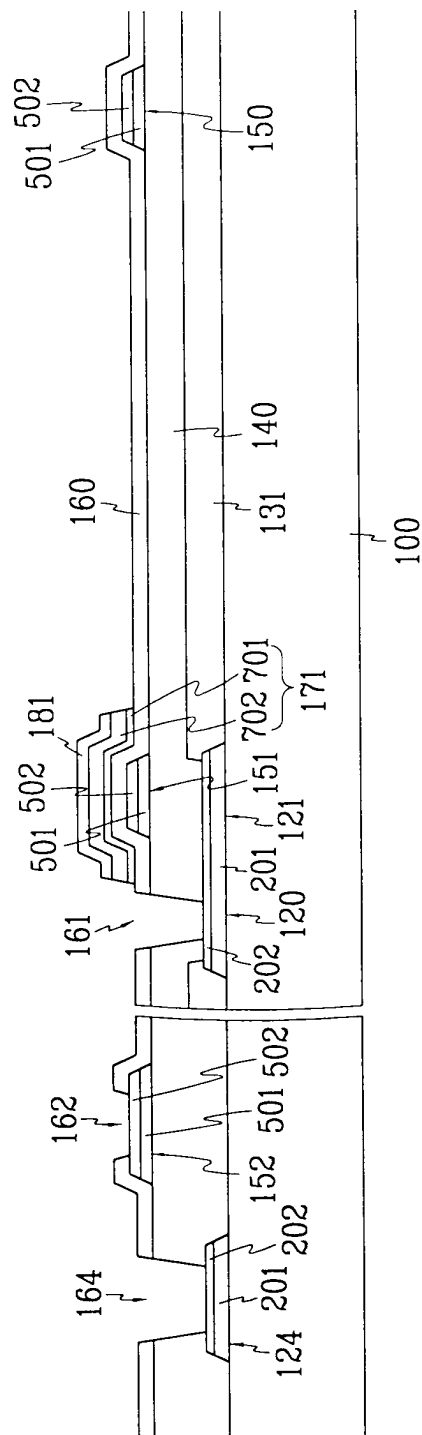


FIG. 25

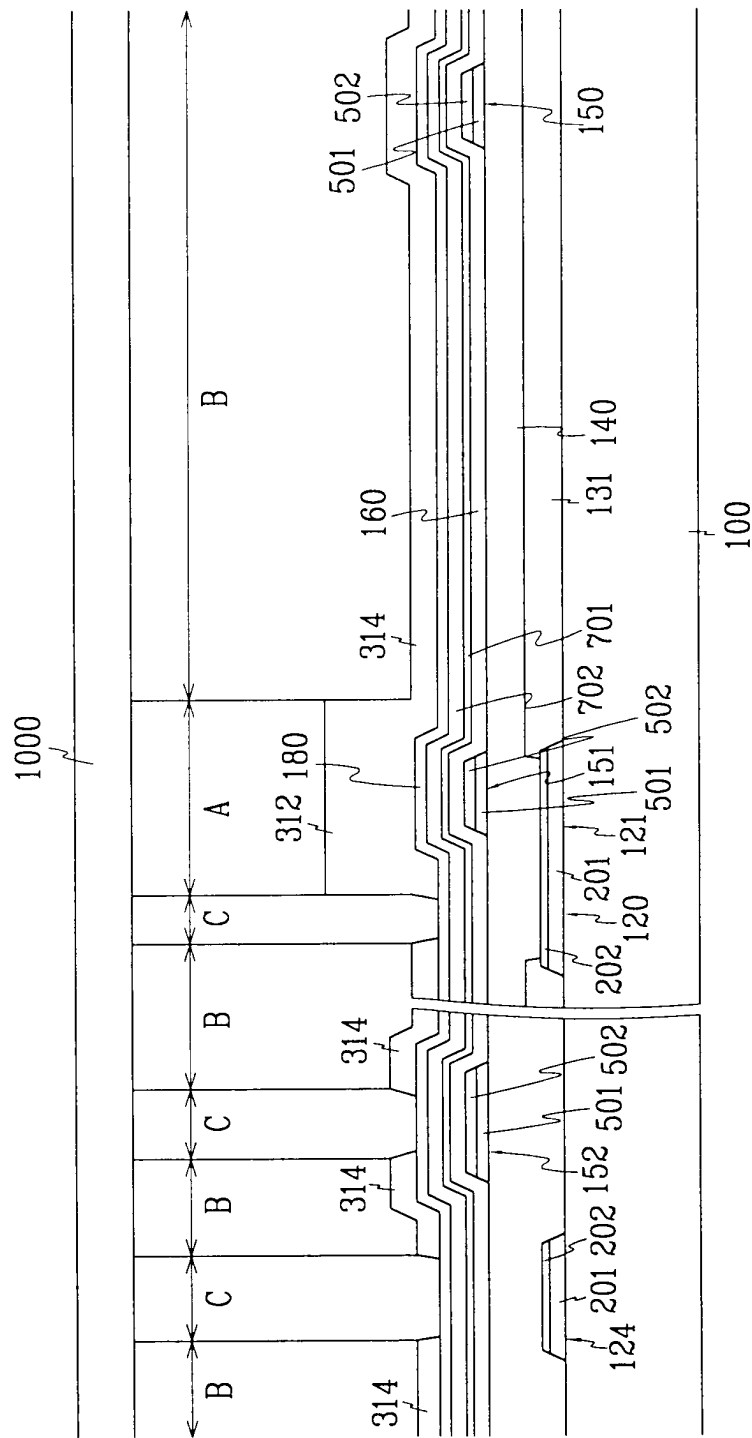
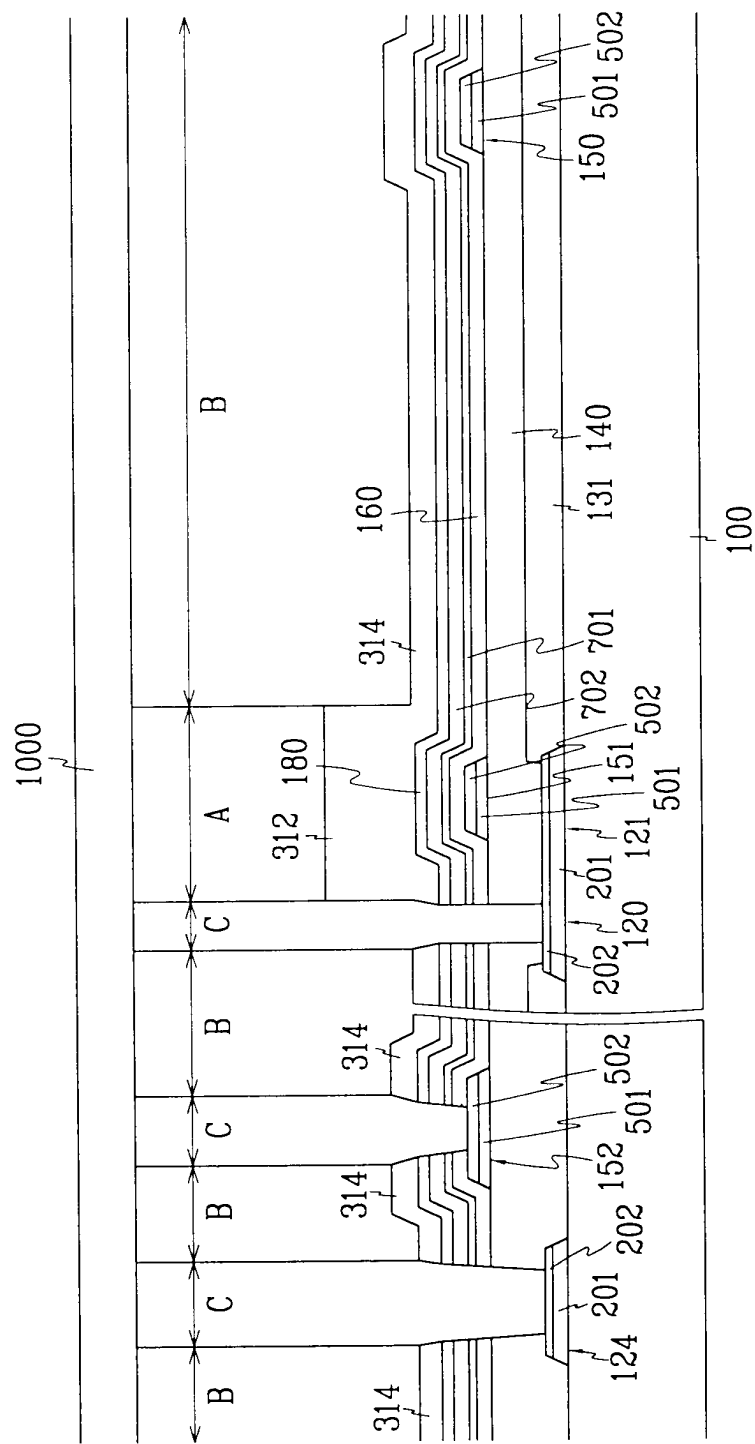


FIG.26



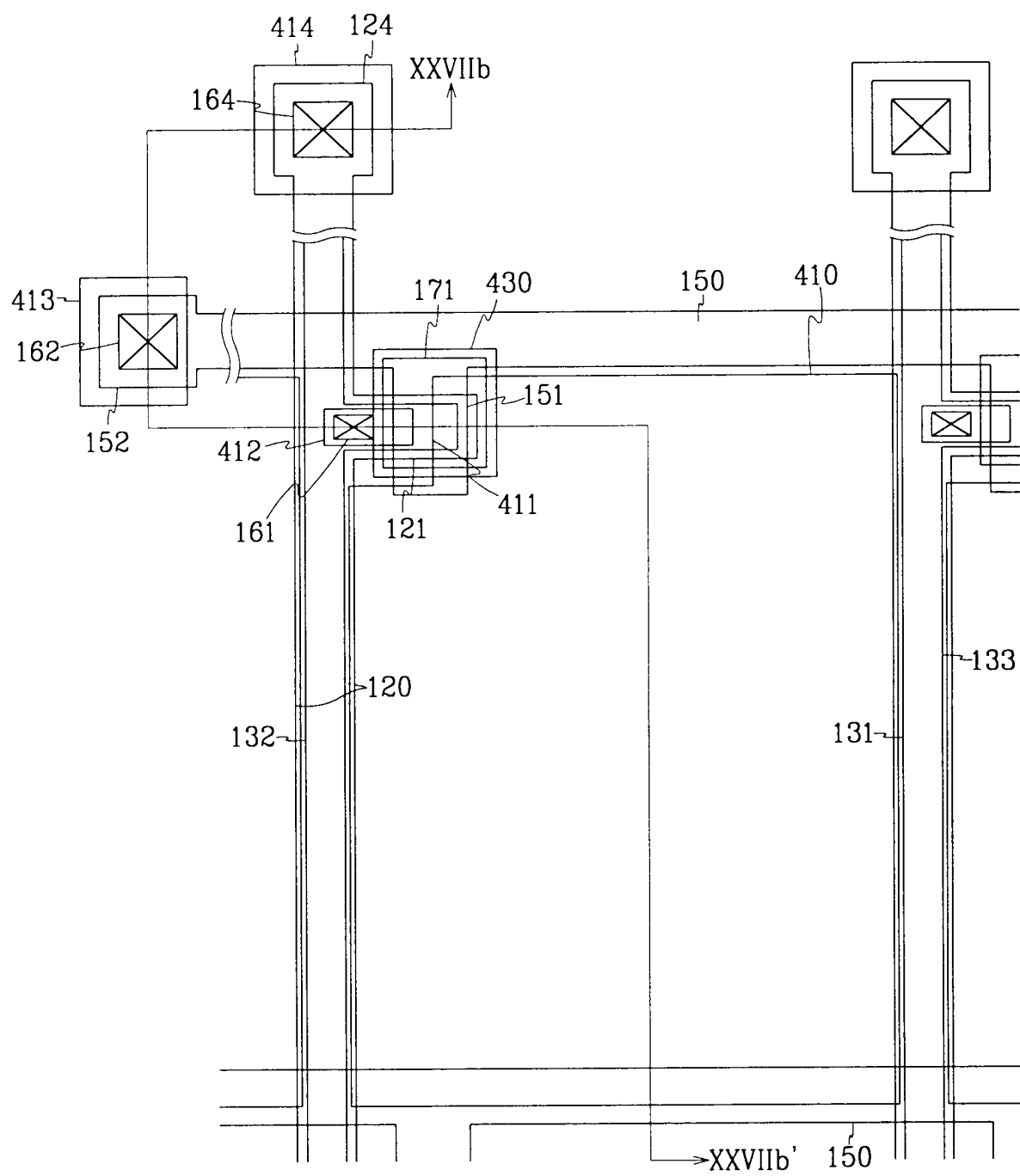
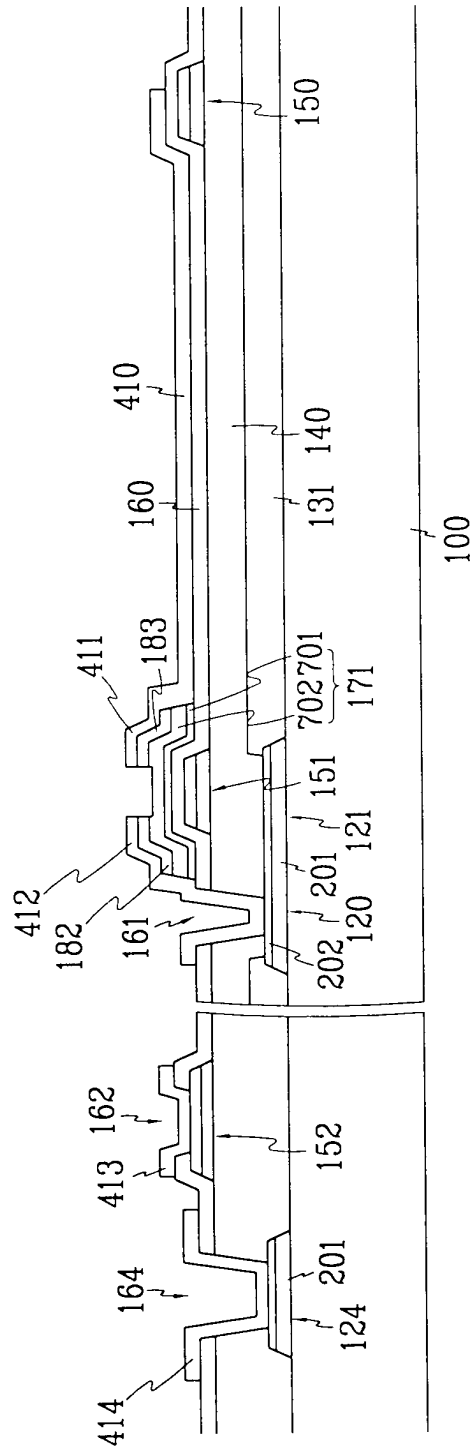


FIG. 27B



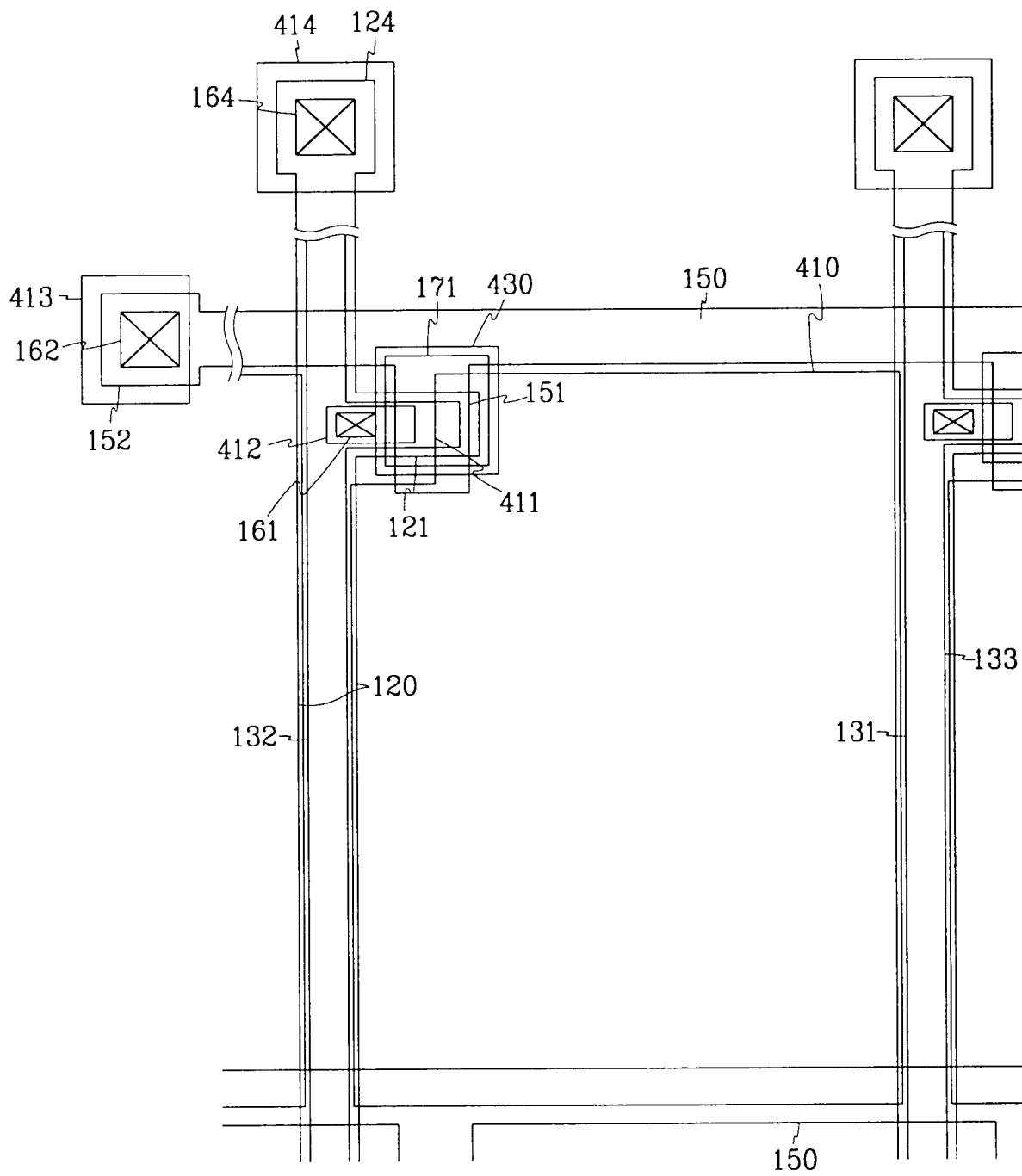




FIG. 29

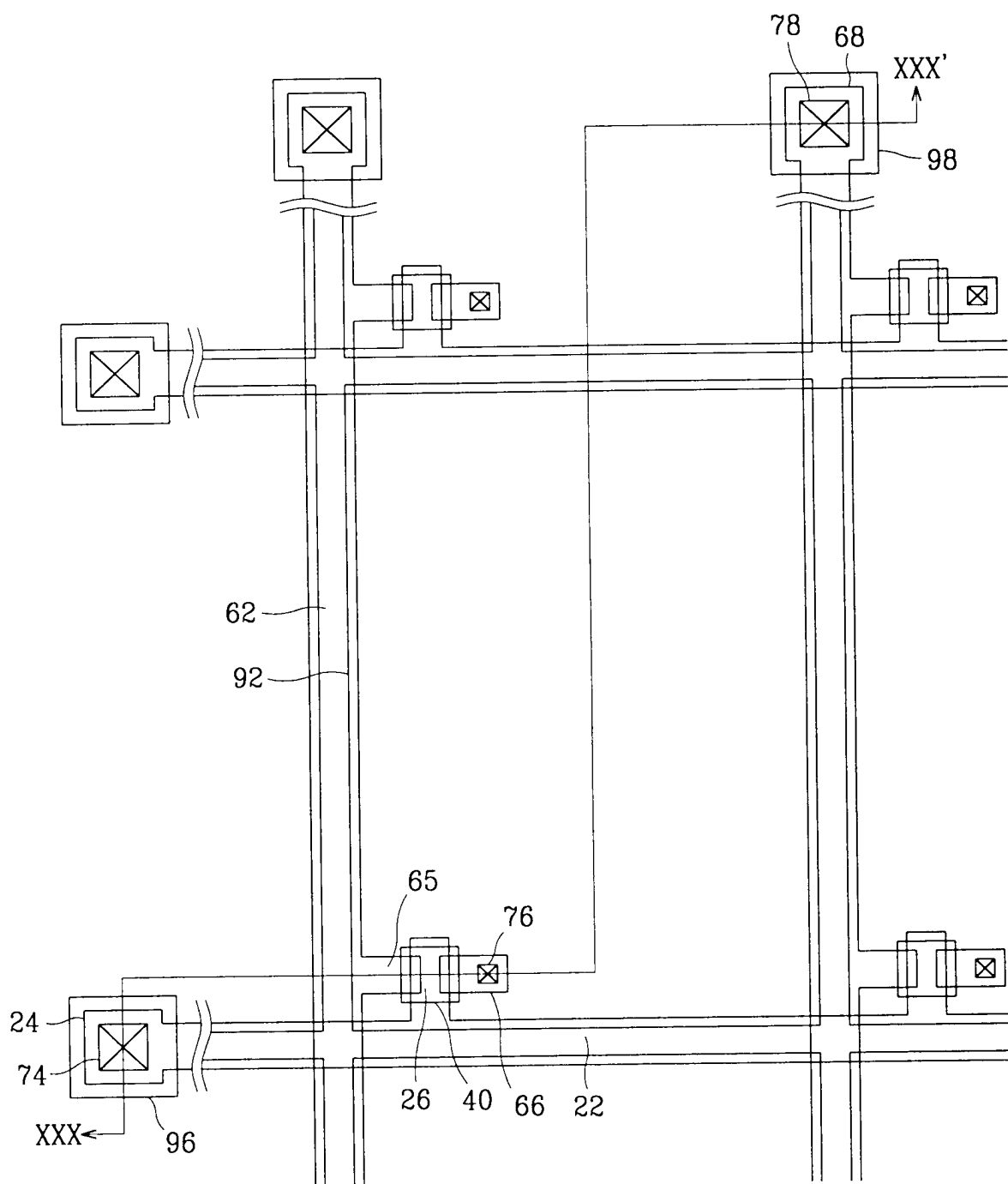


FIG.30

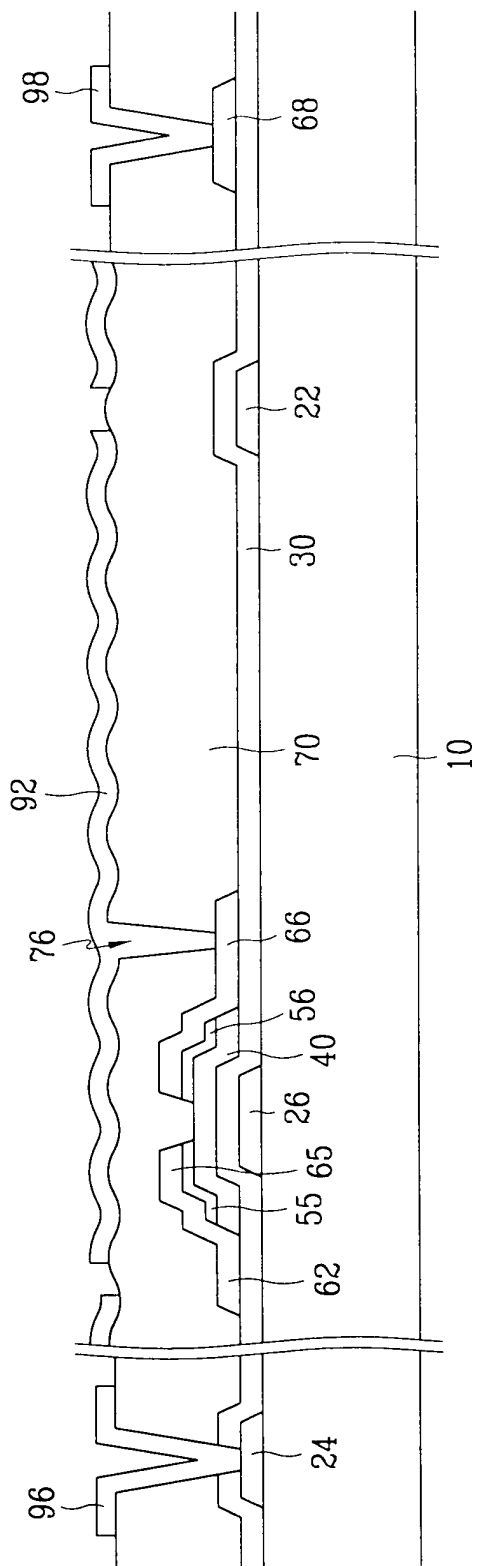


FIG.31A

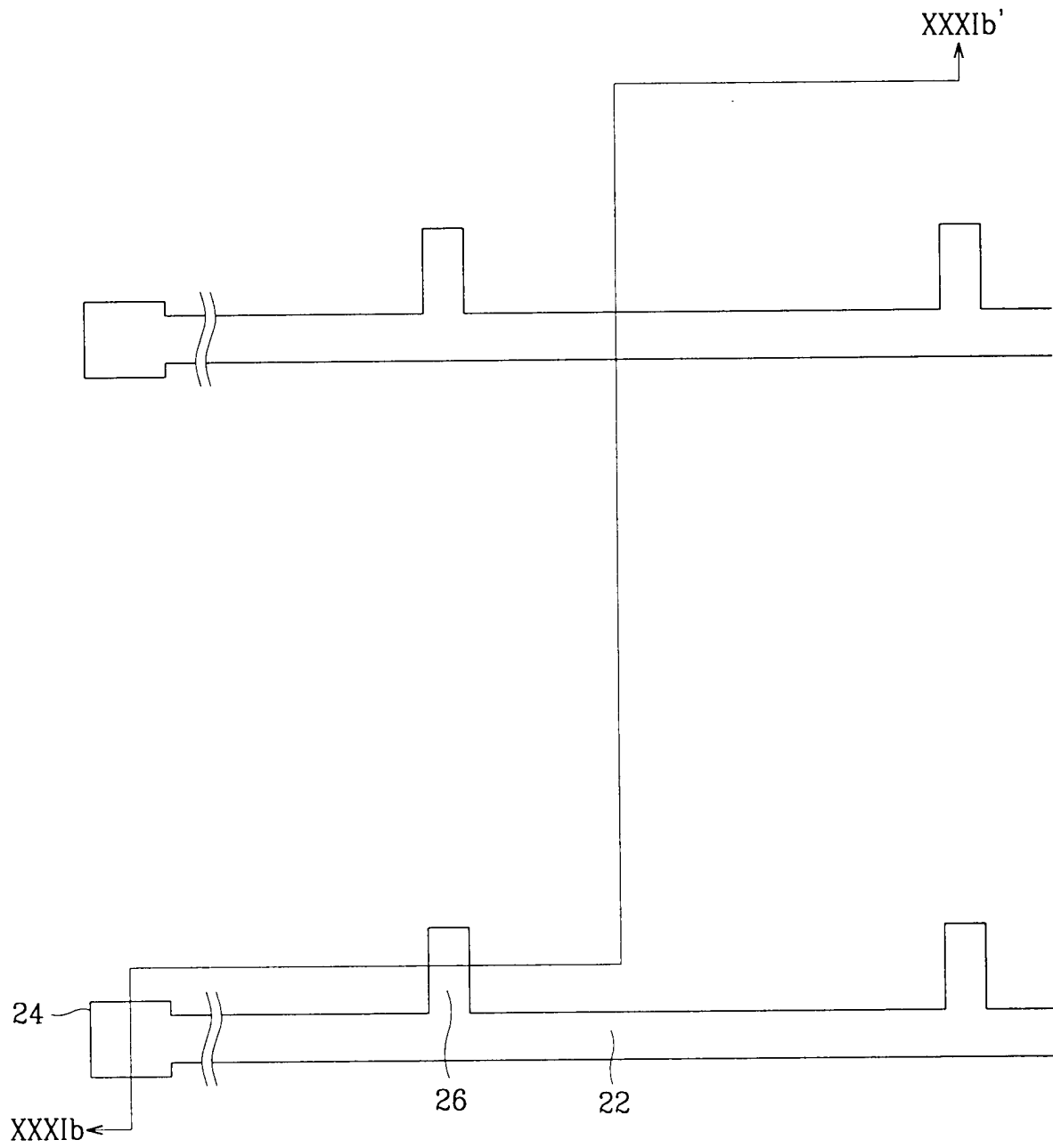


FIG. 31B

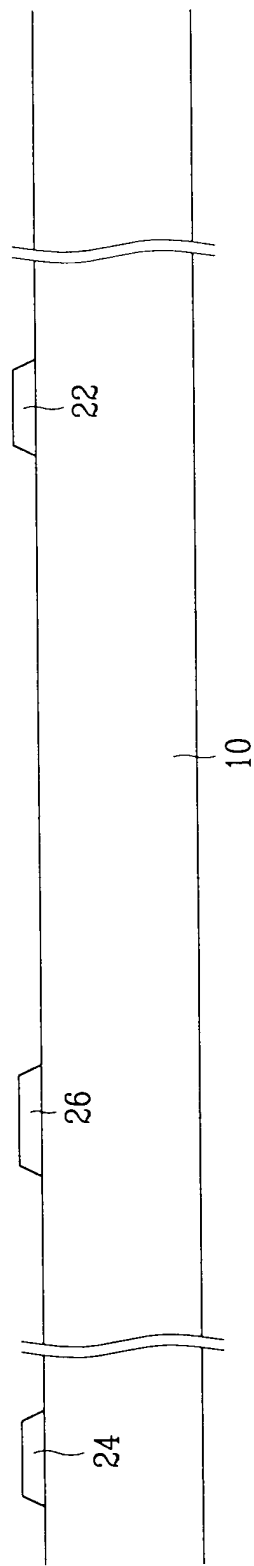


FIG.32A

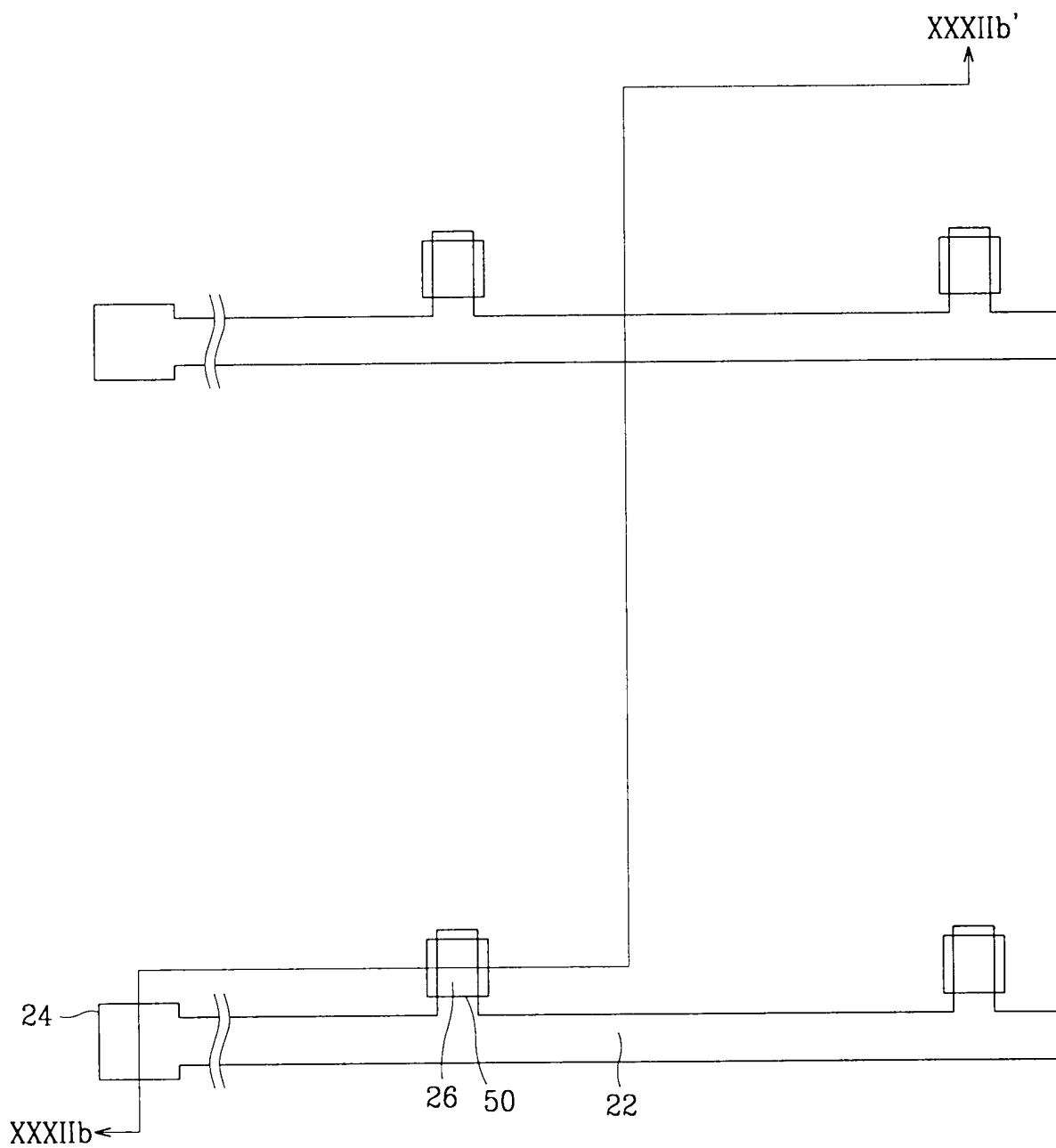


FIG. 32B

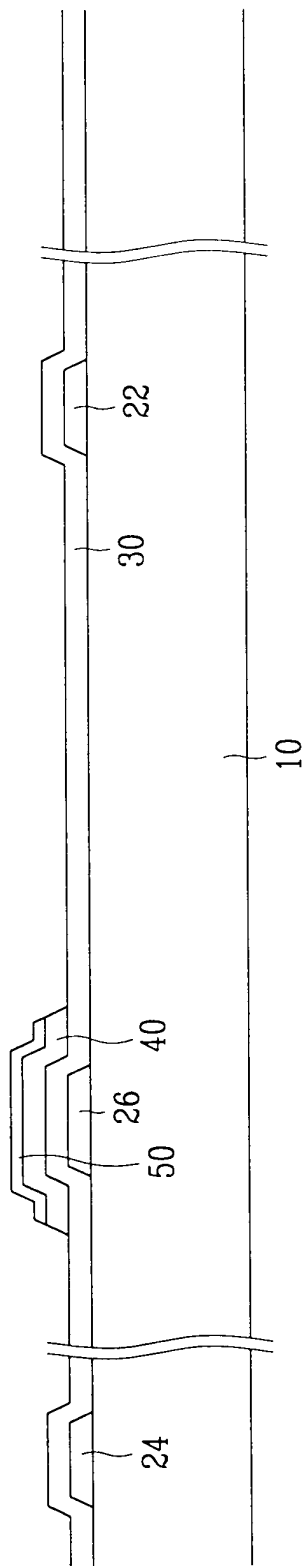


FIG.33A

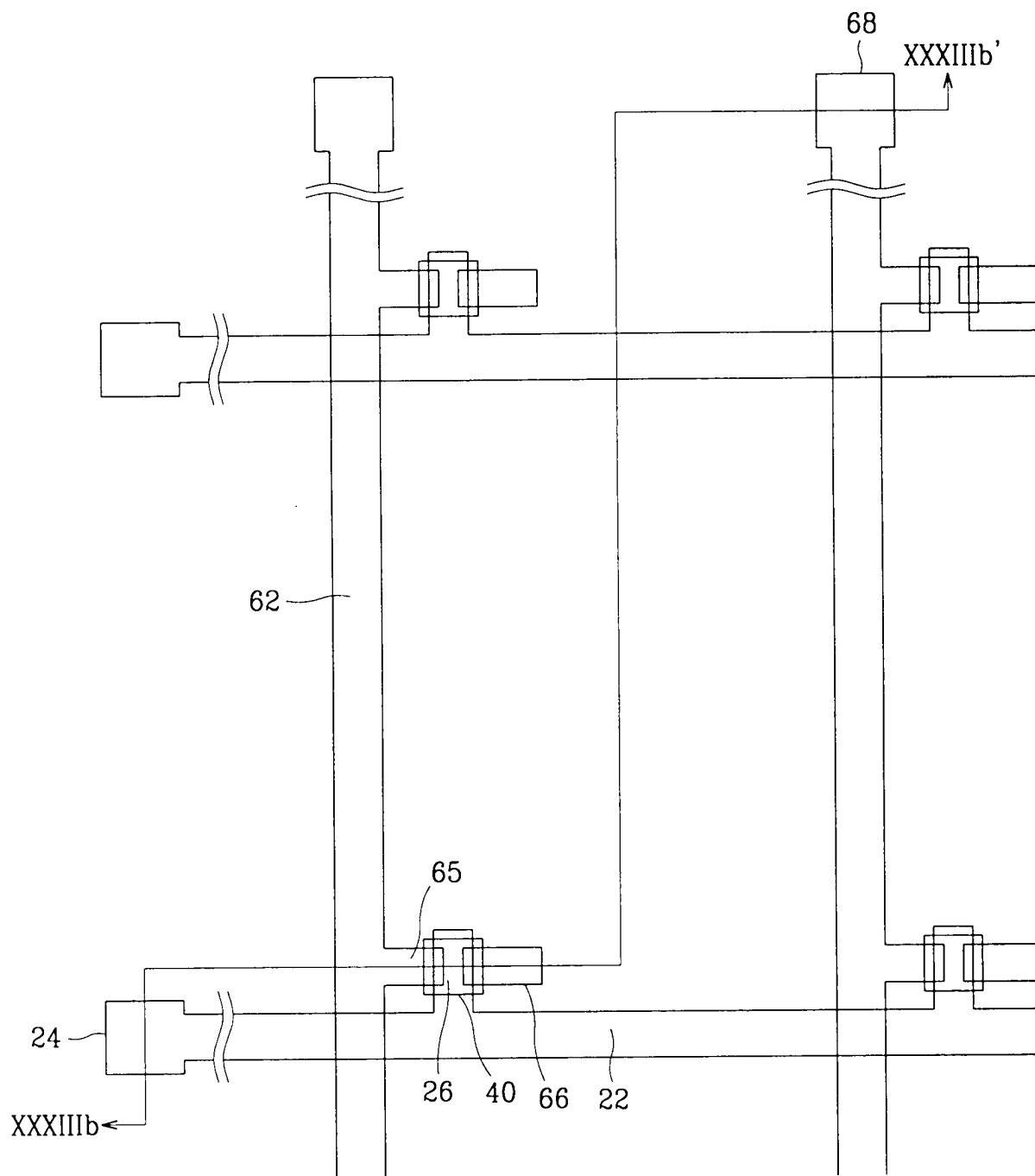


FIG. 33B

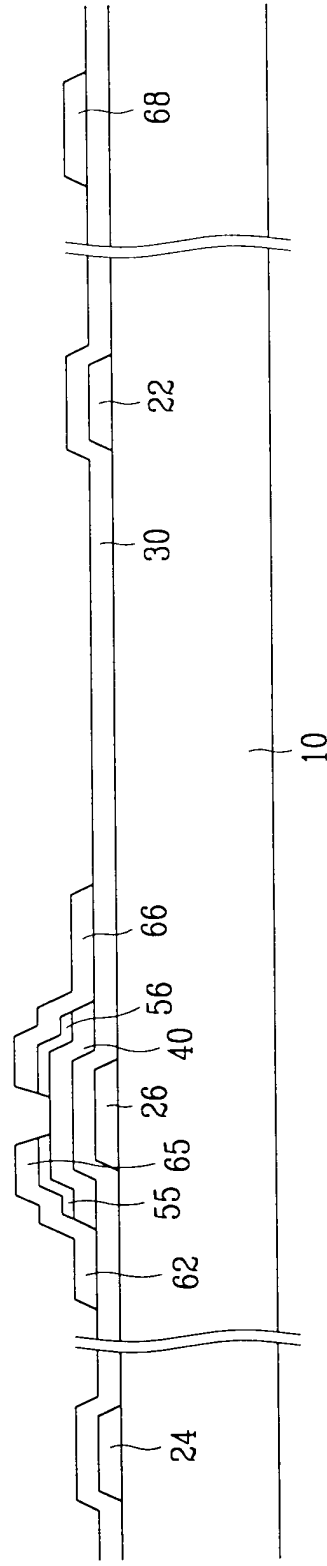




FIG. 34A

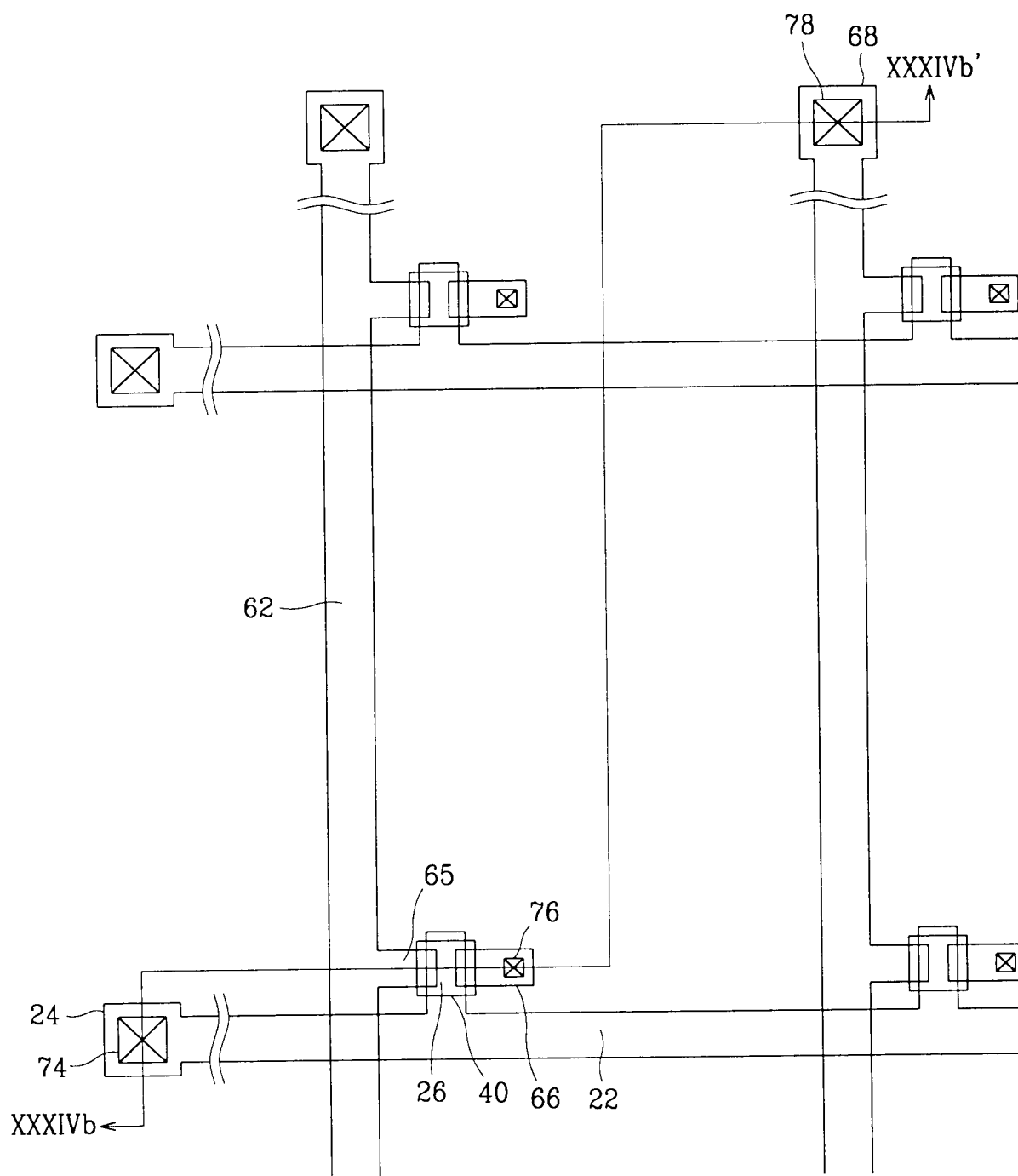


FIG. 34B

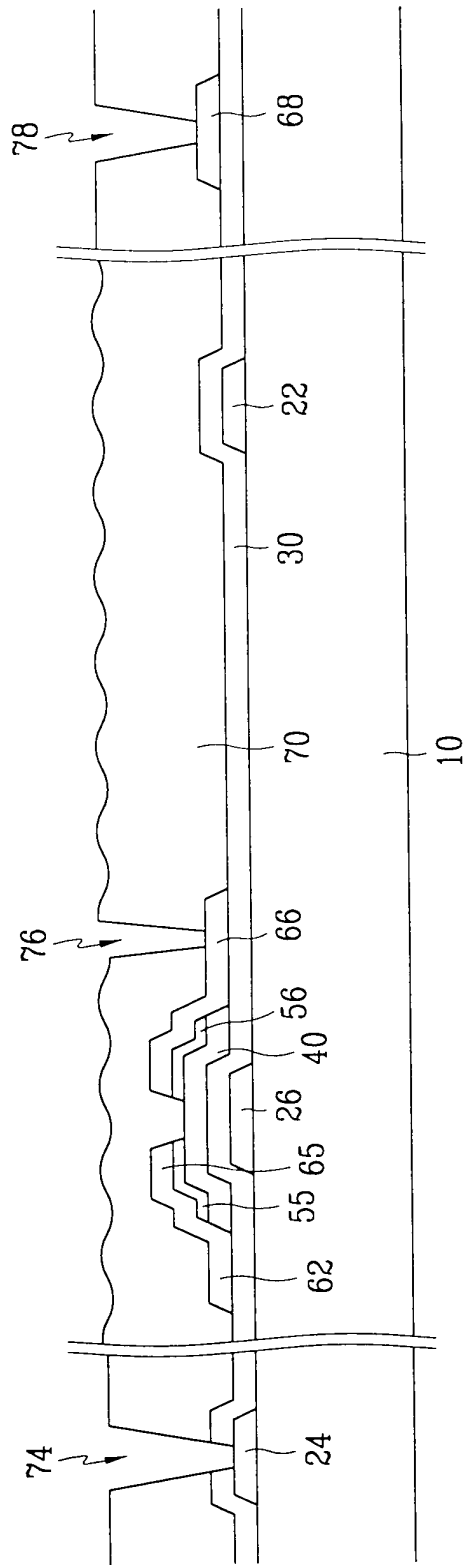


FIG. 35

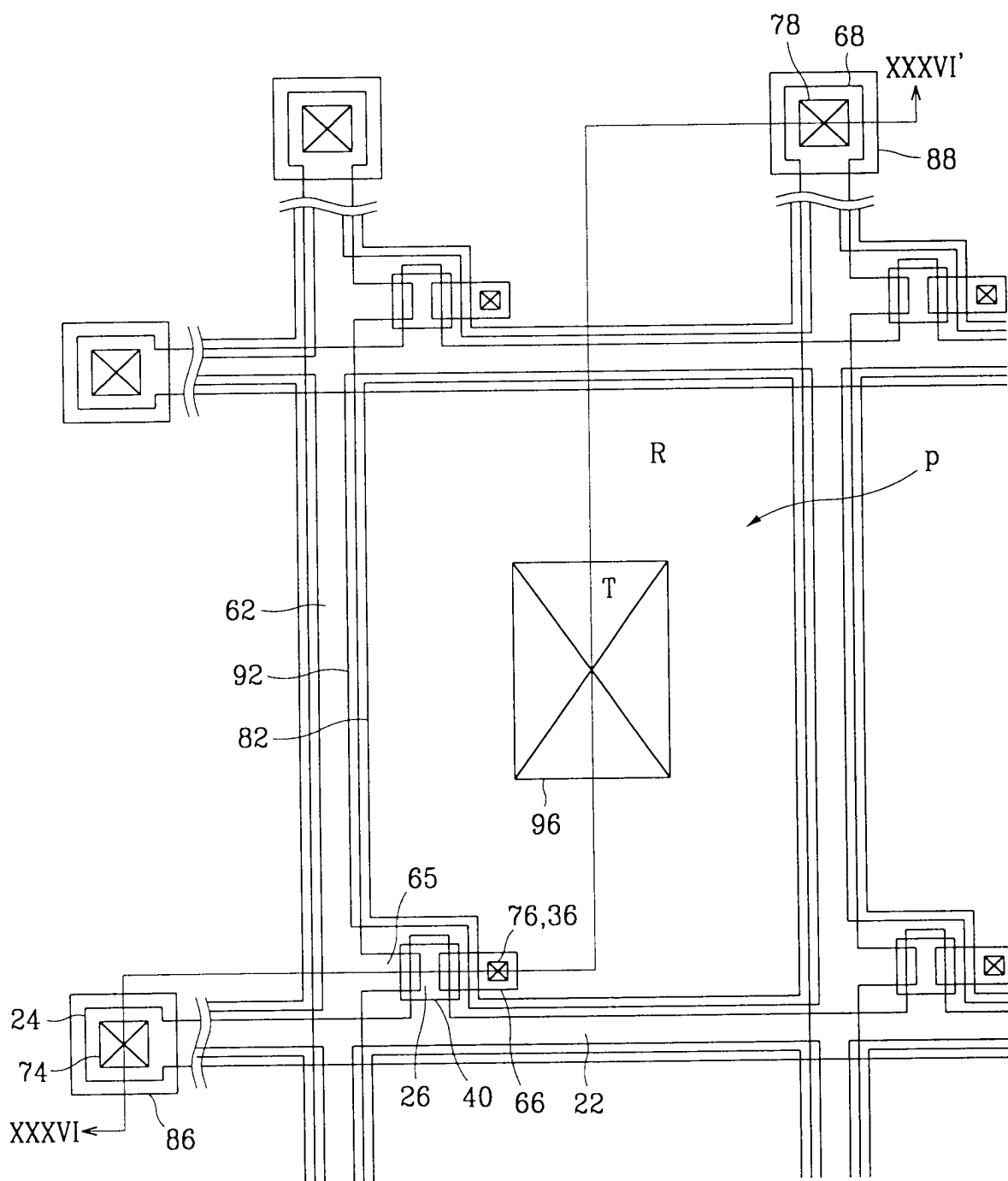


FIG.36

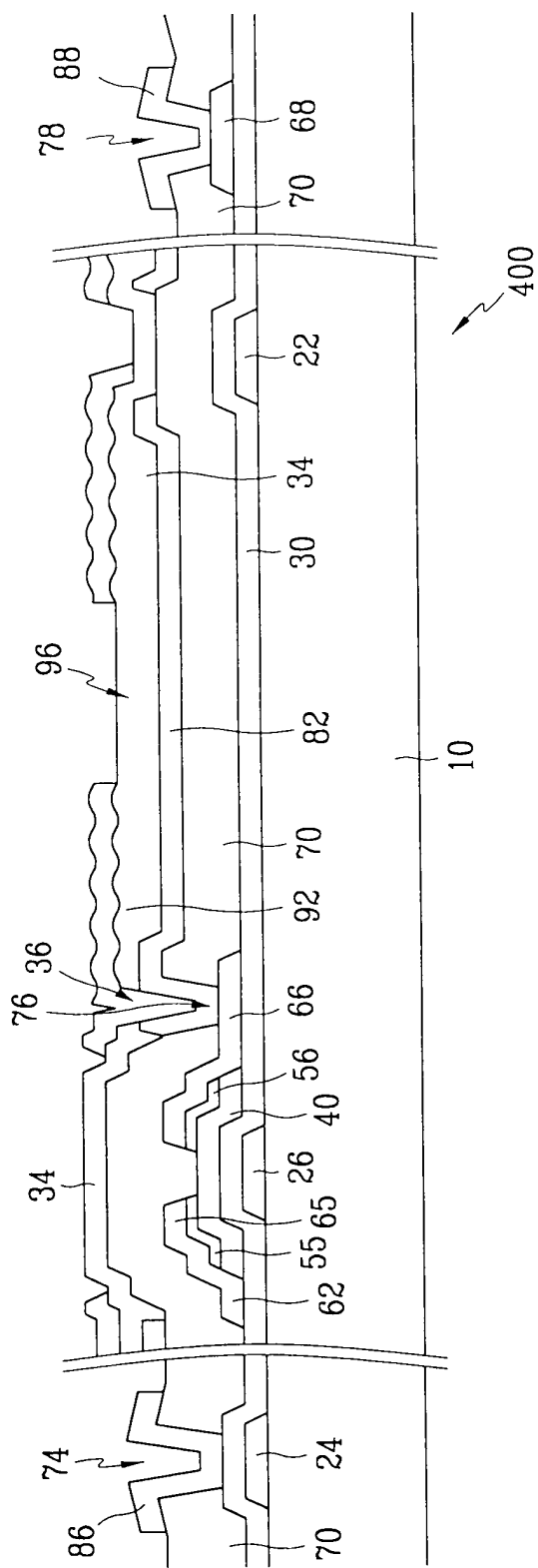


FIG.37A

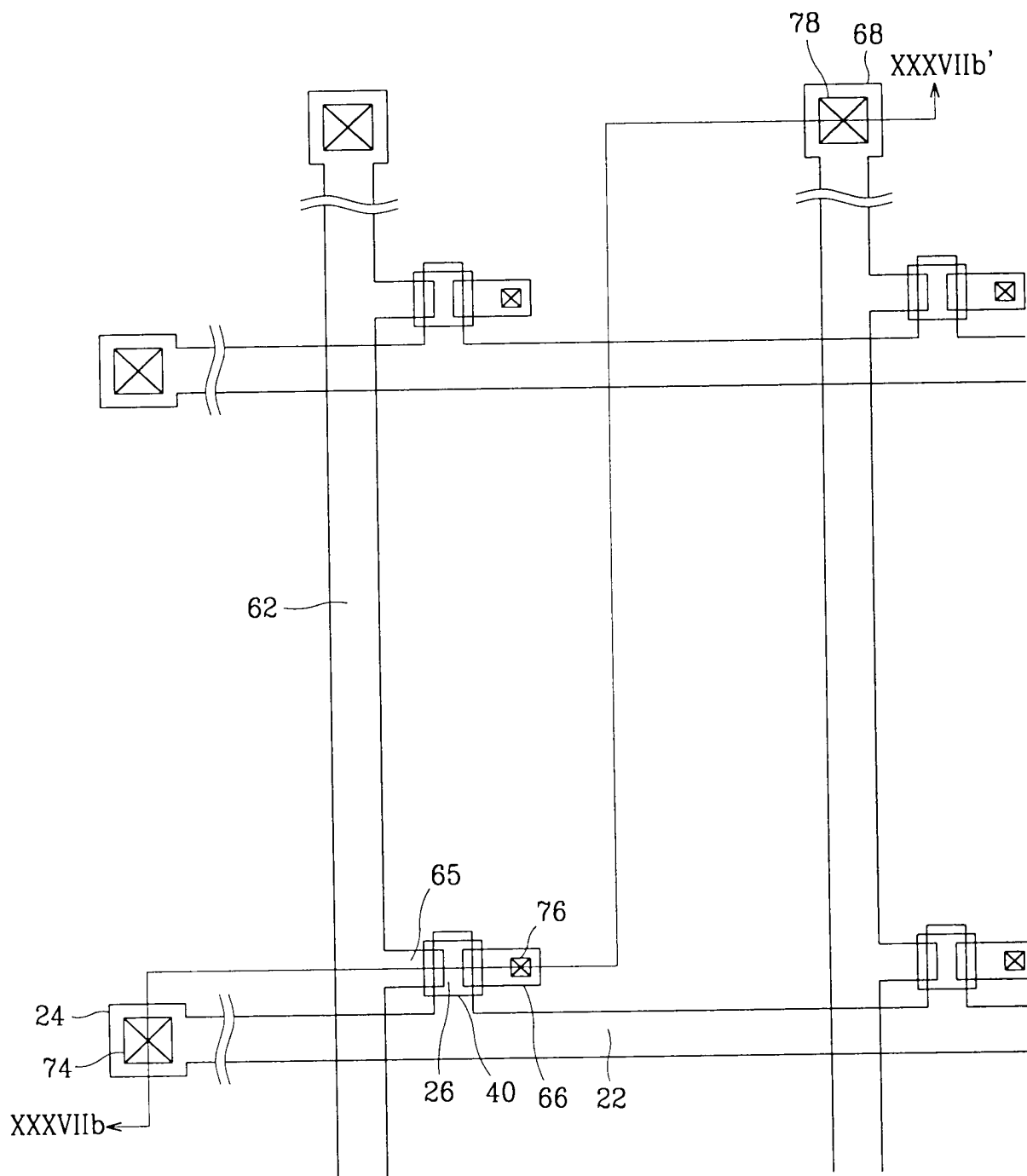


FIG. 37B

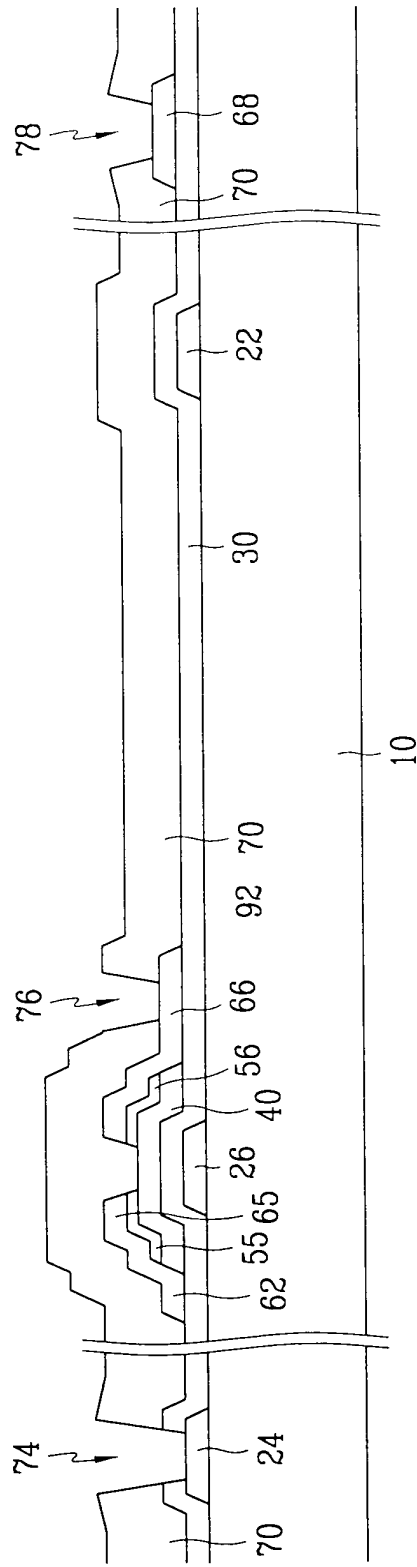


FIG.38A

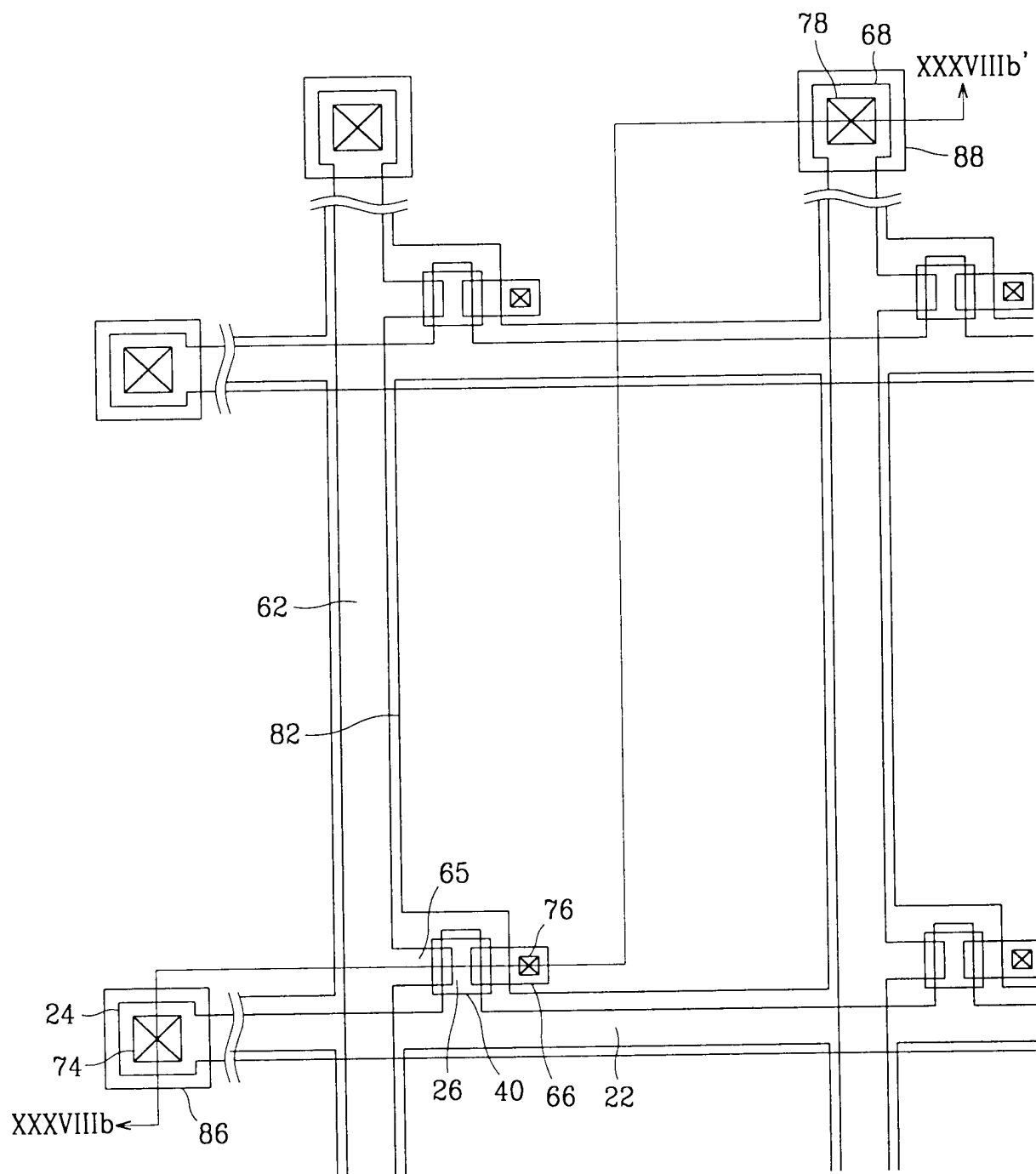


FIG. 38B

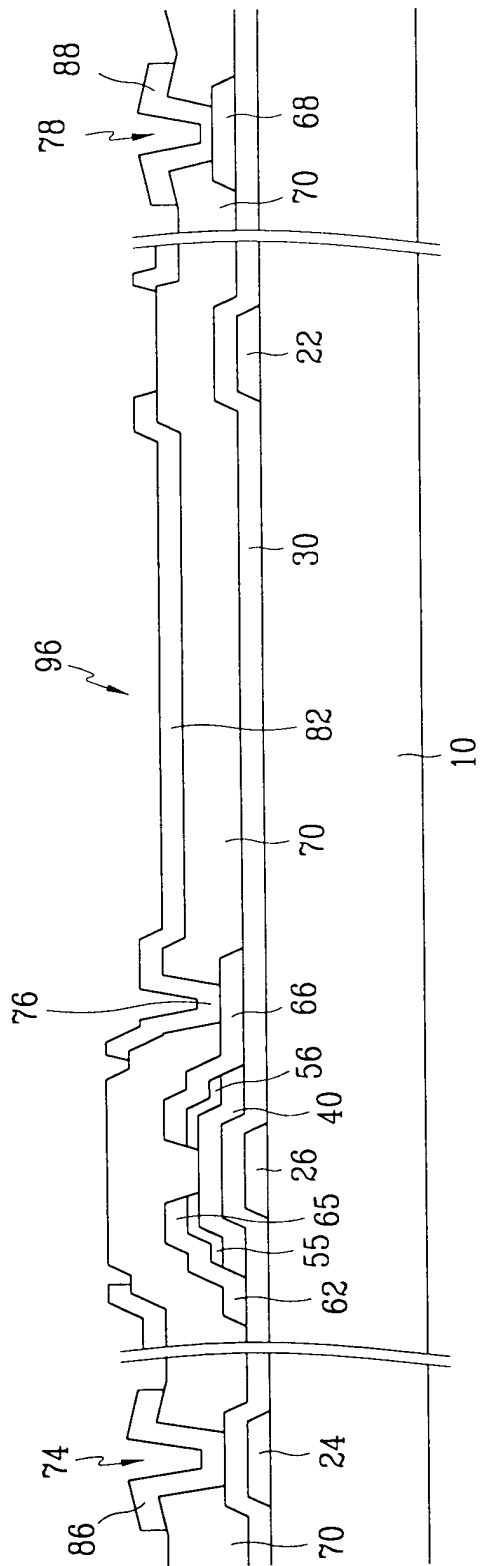




FIG. 39A

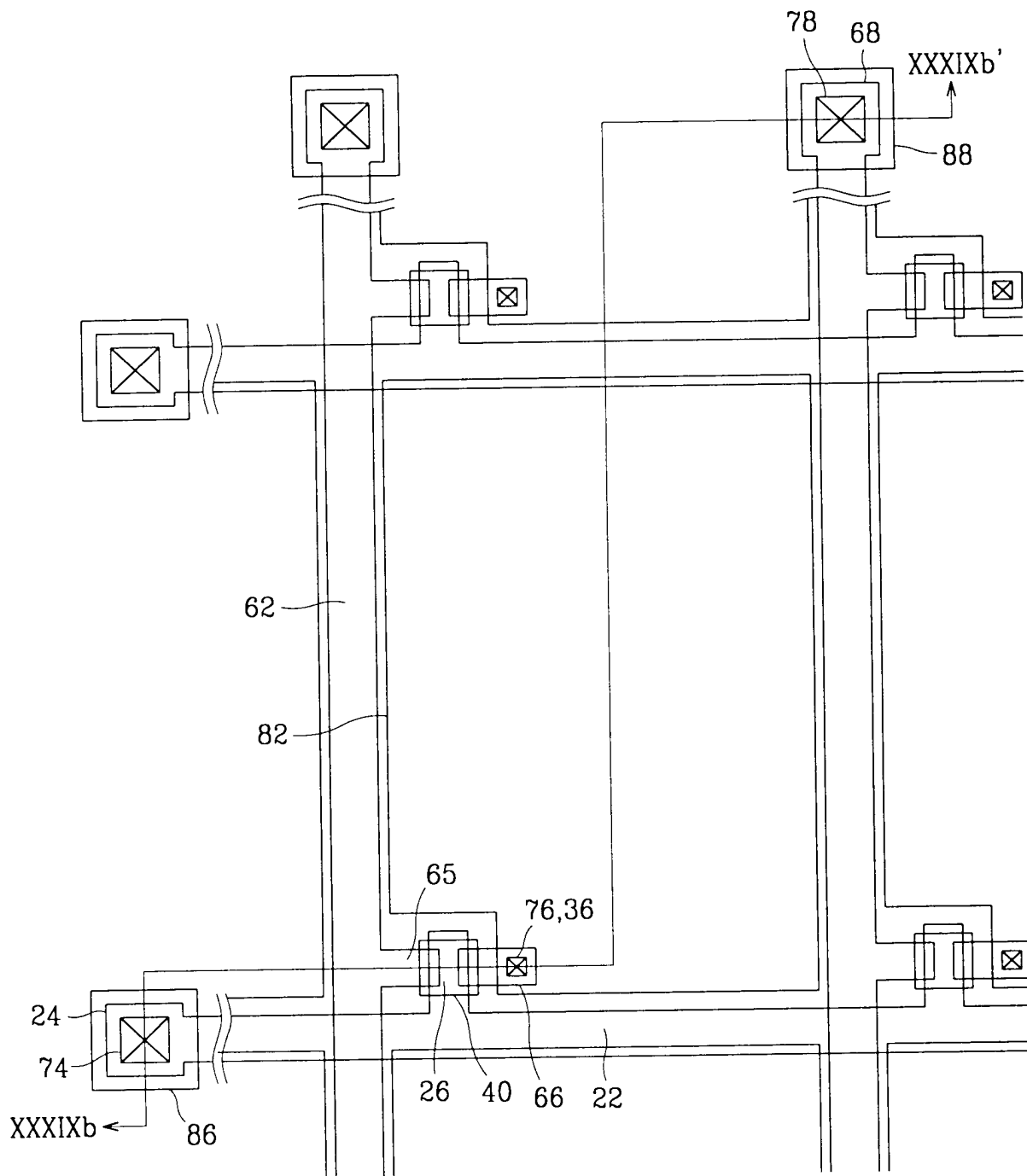


FIG. 39B

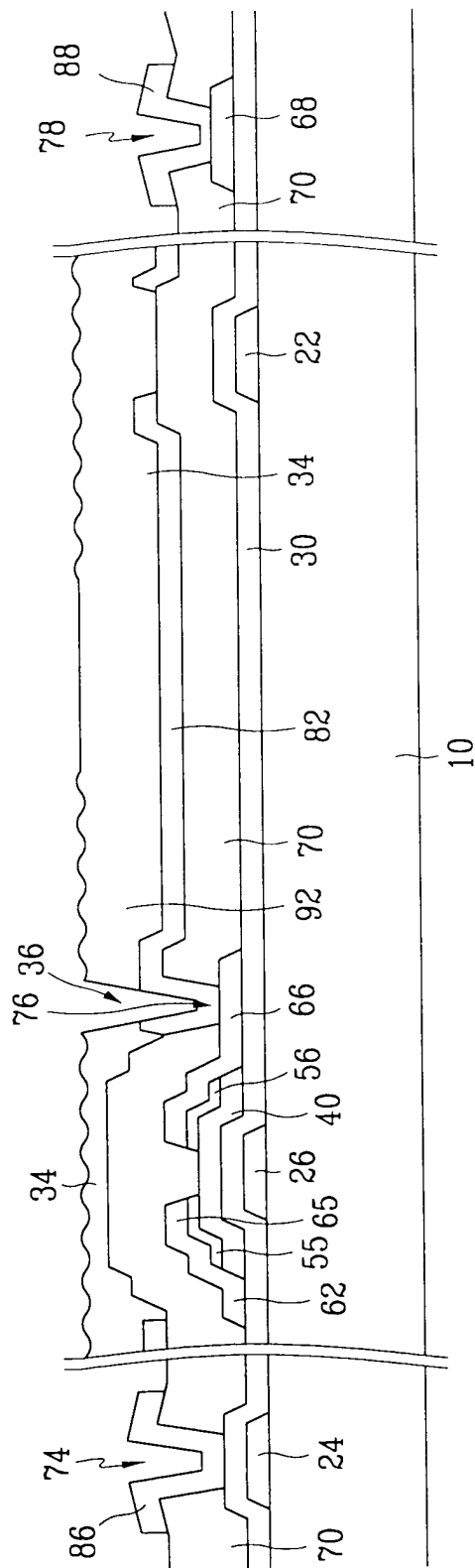


FIG. 40

